

# First International Computer, Inc

## Protable Computer Group    HW Department

Board name : Mother Board Schematic

Project : KR2W\_K8\_ATI RS482M+SB450

Version : 0.1(ES)

Initial Date : 03.09.2005

1. Schematic Page Description :
2. PCI & IRQ & DMA Description :
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9. switch setting

Manager Sign by :

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LAN Circuit check by : Vivian Chen

Audio Circuit check by : Annie Wang

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<b>TITLE</b>			
Size C	Document Number <b>KR2W &lt; AMD K8 + RS482M + SB450 &gt;</b>		Rev 0.1
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# 1. Schematic Page Description :

## KR2W Schematic Ver : 0.1

1. Title

2. Schematic Page Description

3. Block Diagram

4. ANNOTATIONS

5. K8\_Claw Hammer(1/3)

6. K8\_Claw Hammer(2/3)

7. K8\_Claw Hammer(3/3)

8. CPU CORE

9. Thermal / DRAM POWER

10. CLOCK GEN (ICS951416)

11. RS482M Host (1/4)

12. RS482M\_VIDEO (2/4)

13. RS482M\_ALINK/PCIE (3/4)

14. RS482M\_POWER (4/4)

15. DDR SO-DIMM

16. DDR PULL UP

17. SB450 PCI(E)/LPC (1/4)

18. SB450 IDE/ S\_ATA(2/4)

19. SB450 ACPI/AC97/US(3/4)

20. SB450\_POWER(4/4)
21. LED / PWR SW

22. VIA VT6311S (1394)

23. GL817E(Card-Reader)

24. New Card(express card)

25. CRT Port

26. TV Port

27. LCD CNN

28. PMU08

29. RTC/ MDC CNN

30. ASIC-C0

31. CPU PWR OK

32. SATA HD / CD-ROM CNN

33. PATA HD FPC-CNN

34. Calexico MINI PCI

35. USB CNN

36. FirmWare Hub

37. LPC KBC (M3886)

38. PCI/LPC Pullup/Down

39. DIP/LID SW; SCREW

40. PCI/IDE Reset Circuit
41. LAN(RTL8101L)

42. AUDIO CODEC(ALC260)

43. AUDIO AMP & SPEAKER

44. Headphone & MIC

45. Charger Circuit

46. Battery Voltage Sense

47. Adpin/ Power (PMU3V/5V)

48. 3V, 5V, 2.5VDDS/M

49. 2.5VDDA/1.8VDDA/1.8VDDM

50. 5VDDA/3VDDA

51. 1.2VDDM/1.2VLDT

52. Timing

53. Schematic History

54. LAYOUT DESIGN GUIDE

# 2. PCI & IRQ & DMA Description :

IDSEL	CHIP
AD21	Mini PCI(Wireless LAN)
AD20	CardBus (CB1410)

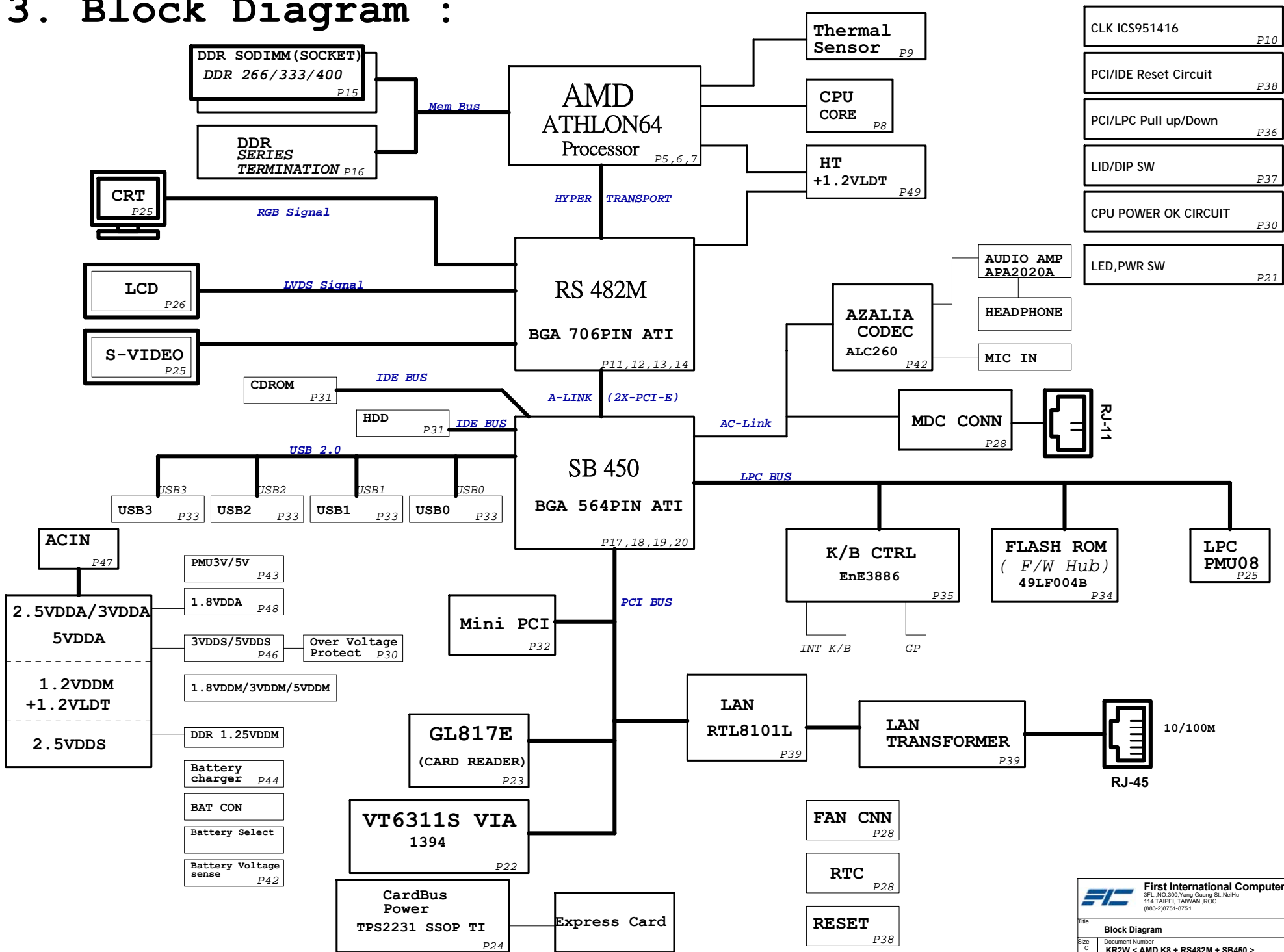
PCIINT	CHIP
IRQA	VGA/LAN
IRQB	CardBus (CB1410)
IRQC	MiniPCI
IRQD	MiniPCI

BUSMASTER	REQ	CHIP
	REQ0 / GNT0	Mini PCI(Wireless LAN)
	REQ1 / GNT1	CardBus (CB1410)
	REQ2 / GNT2	Mini PCI(Wireless LAN)
	REQ3 / GNT3	—
	REQ4 / GNT4	—

IRQ Channel	Description
IRQ0	System timer
IRQ1	Keyboard
IRQ2	(Cascade)
IRQ3	LAN / MODEM
IRQ4	Serial Port
IRQ5	AUDIO / VGA / USB
IRQ6	FLOPPY DISK
IRQ7	LPT
IRQ8	RTC
IRQ9	ACPI
IRQ10	FIR (Disable by default) (MODEM/LAN)
IRQ11	Cardbus
IRQ12	PS/2 mouse
IRQ13	FPU
IRQ14	HDD
IRQ15	CDROM

DMA Channel	Device
DMA0	FIR (disable by default) (MODEM / LAN)
DMA1	ECP
DMA2	FLOPPY DISK
DMA3	AUDIO
DMA4	(Cascade)
DMA5	Unused
DMA6	Unused
DMA7	Unused

### 3. Block Diagram :



# 4. Net name Description :

# 5.Board Stack up Description

## Voltage Rails

DCIN	Primary DC system power supply
PMU5V	5.0V always on power rail by LATCH or ACIN
PMU3V	3.3V always on power rail by LATCH or ACIN
5VDDA	5.0V always on power rail by DCON or PSUSC0
3VDDA	3.3V always on power rail by DCON or PSUSC0
2.5VDDA	2.5V always on power rail by DCON or PSUSC0
5VDDS	5.0V power rail
3VDDS	3.3V power rail
2.5VDDS	2.5V power rail
2.5VDDS CPU	2.5V power rail for CPU&DDR
DDR_1.25VDDS	1.25V DDR Termination Voltage
12VDDM	12V switched power rail
5VDDM	5.0V switched power rail
3VDDM	3.3V switched power rail
2.5VDDM	2.5V switched power rail
1.5VDDM	1.5V power rail 0.8 ~ 1.55V
Vcore CPU	Core Voltage for CPU
+1.2VLDT	VCC For CPU & NB Hyper Transport

## Part Naming Conventions

C	= Capacitor
CN	= Connector
D	= Diode
F	= Fuse
L	= Inductor
Q	= Transistor
R	= Resistor
RP	= Resistor Pack
U	= Arbitrary Logic Device
Y	= Crystal and Osc

## Net Name Suffix

0	= Active Low signal
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## Signal Conditioning

_D_	= Damped (by a resistor)
_Q_	= Isolated (by a Q-switch)
_L_	= Filtered (by an inductor or bead)

## PCB Layers

Layer 1	TOP
Layer 2	GND
Layer 3	IN1/Mixer
Layer 4	IN2/Mixer
Layer 5	VCC
Layer 6	BOTTOM

POWER RAIL	DESTINATION	VOLTAGE	S0 CURRENT
VCORE_CPU	K8	0.8~1.55V	42A
+1.2VLDT	K8	+1.2V	??A
2.5VCCA	K8 PLL	2.5V	??A
1.5VDDM	NB CORE & PLL	1.5V	??A
1.25VDDS	DDR RAM TERMINAL	1.25V	0.0769A
2.5VDDS_CPU	CPU & DDR RAM		1.046A (Idle) 1.692A (Run) 3DMark)
2.5VDDM	SB CORE & USBPLL & MII LVDS	2.5V	??A
2.5VDDS	SB USB & MII (SUS)	2.5V	??A
2.5VDDA	SB WAKE UP (SUS)	2.5V	??A
3VDDM	NB VGA	1.5V	0.0675A
	ENE 1410	3.3V	0.528A
	MiniPCI		0.13A
	FWH BIOS		
	LPC KBC		0.0308A (Idle)
	AC97 CODEC		0.0461A (Idle)
	CLK GEN		0.36A
3VDDS	ENE 1410	3.3V	0.36A
	VT6103L		
	MiniPCI		
	PCMCIA VCCA		
3VDDA	SB (SUS)	3.3V	0.165A
5VDDM	AMP2020		0.0615A (Idle) 0.338A (Run)
	CDROM		0.0461A (Idle) 0.677~0.8A (Run)
	HDD		0.0461A (Idle) 0.492A (Run)
	INT KB/ INT MS		
	INVERTER		0.0615A (Idle) 0.569A (Run)
5VDDS	PCMCIA VCCA		
5VDDA	SWITCHING POWER VCC		10UA
PMU3V	PMU08		0.0615A
PMU5V	ASIC_C0		0.0615A

# ClawHammer HT Interface

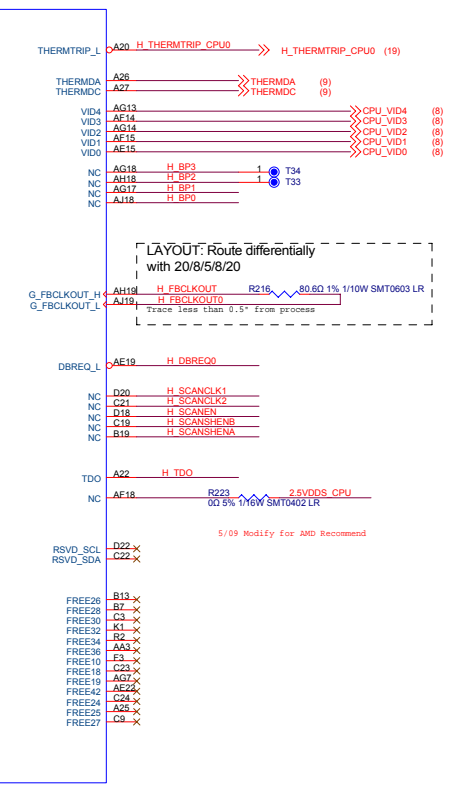
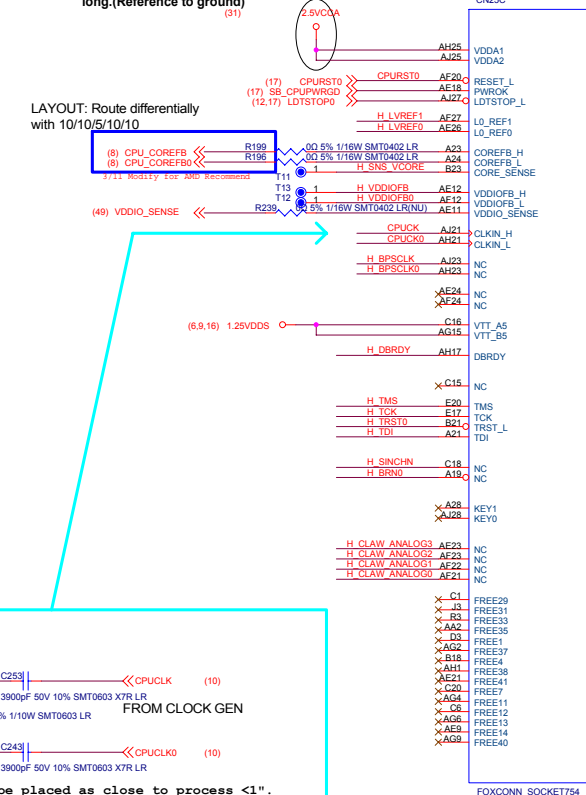
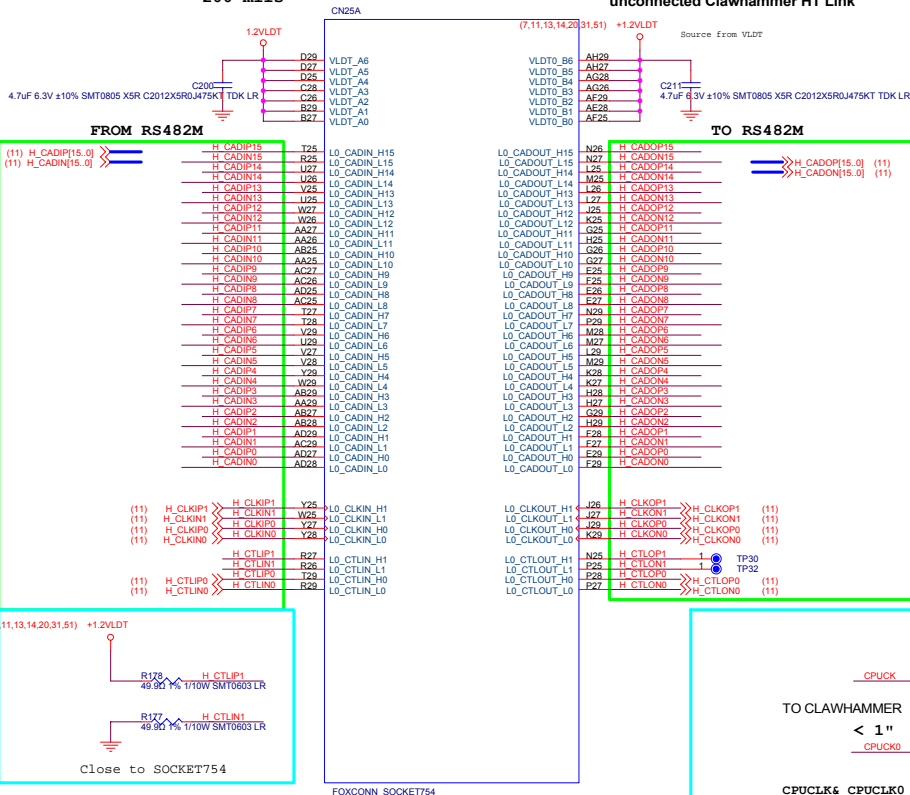
200 mils

LAYOUT: Place HT bypass caps on topside near unconnected Clawhammer HT Link

LAYOUT: Route 2.5VCCA approx. 50mil wide and 500mils long.(Reference to ground)

LAYOUT: Route differentially with 10/10/5/10/10

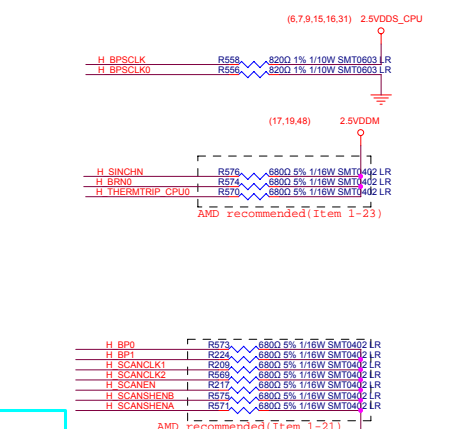
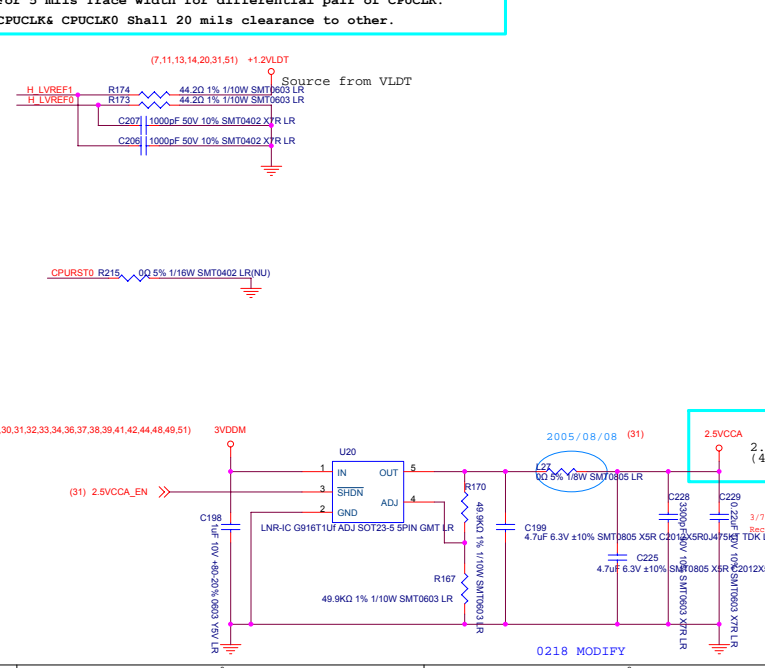
LAYOUT: Route differentially with 20/8/5/8/20



- HT BUS General Routing Rules:**
1. HT BUS is easy to route, and uses minimal board space.
  2. HT BUS length must be greater than 1" and less than 12.0".
  3. All CAD/CTL/CLK within a clock group must route at same layer.
  4. HT BUS is Ground-referenced differential link.
  5. Differential pair length matching within 30 mils.
  6. CAD\_H to CAD\_L length matching within 30 mils.
  7. CAD to CAD length matching within 120 mils.
  8. CAD to CLK length matching within 60 mils.
  9. CLK to CLK length matching within 2700 mils(max).
  10. CAD/CAD# and CTL/CTL# shall be treated identically within a clock group.

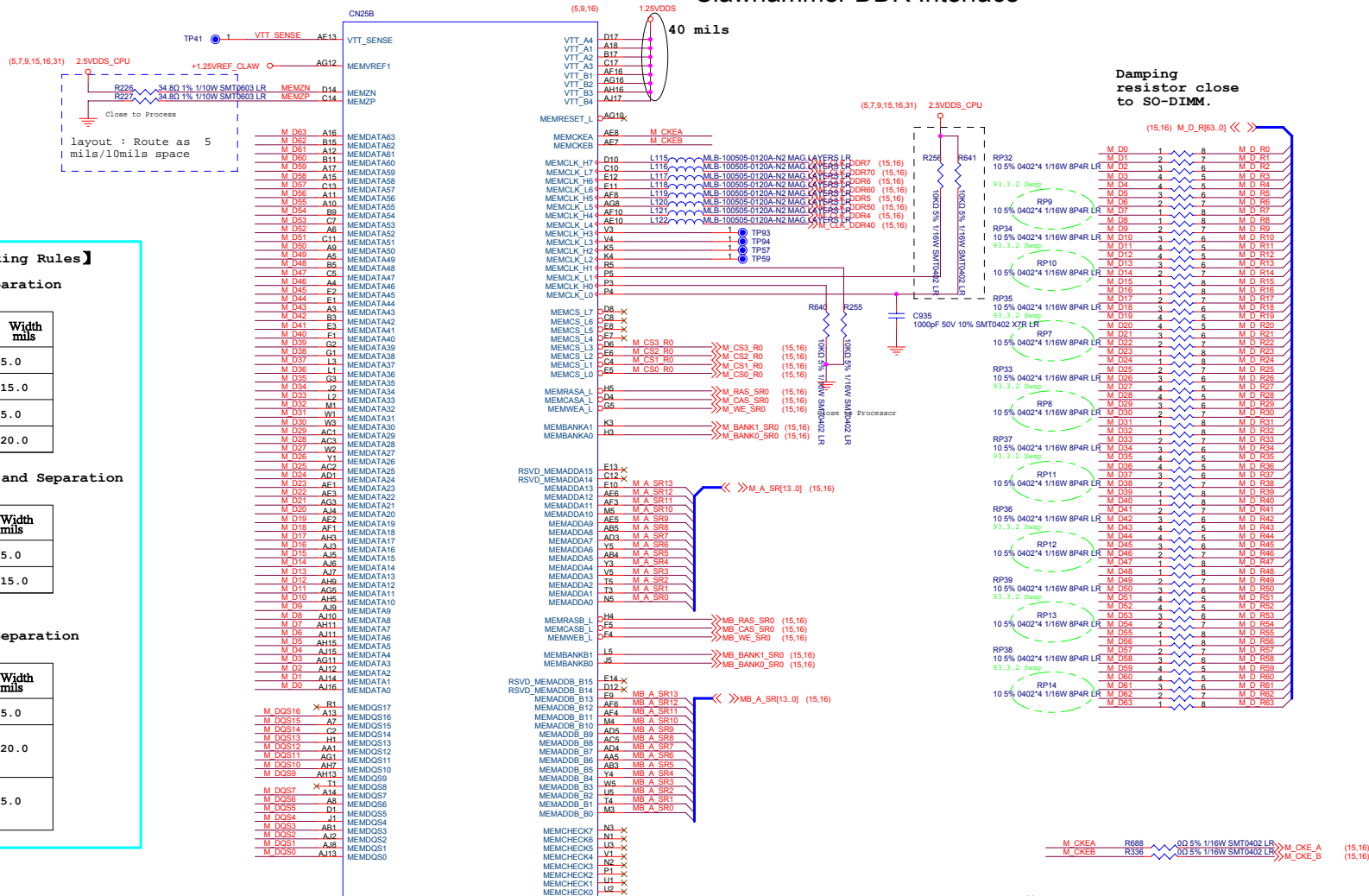
SIGNAL	WSPAC=15mil	5mil
CADIN_H	WDP=5mil	5mil
CADIN_L	WDP=5mil	5mil
SIGNAL	WSPAC=15mil	
SIGNAL	WSPAC=15mil	
H_CLKIP/H_CTLIP	WDP=5mil	5mil
H_CLKIN/H_CTLIN	WDP=5mil	5mil
SIGNAL	WSPAC=15mil	

SIGNAL	WSPAC=15mil	5mil
CADOUT_H	WDP=5mil	5mil
CADOUT_L	WDP=5mil	5mil
SIGNAL	WSPAC=15mil	
SIGNAL	WSPAC=15mil	
H_CLKOP/H_CTLOP	WDP=5mil	5mil
H_CLKON/H_CTLOP	WDP=5mil	5mil
SIGNAL	WSPAC=15mil	

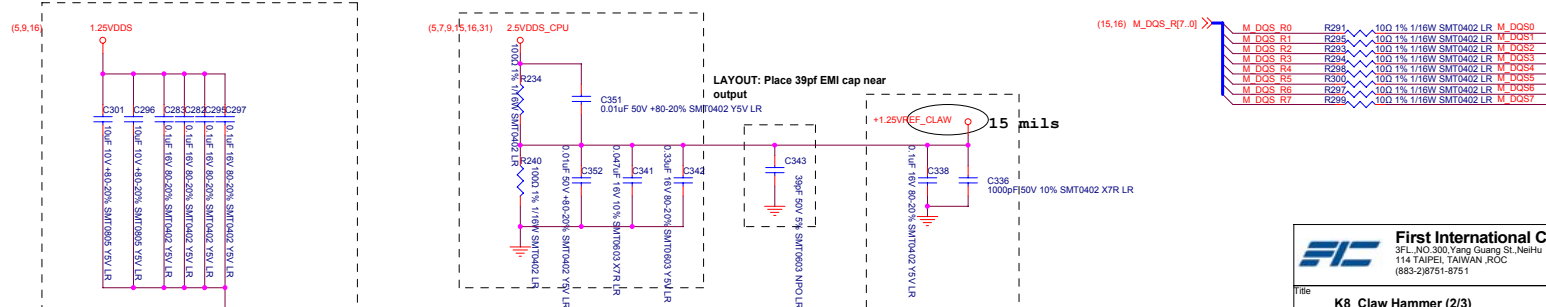


**LAYOUT:** Place on the bottom of the board.

## Clawhammer DDR Interface



Close to Processor



**LAYOUT:** Place on the bottom of the board.

**LAYOUT:** Locate caps close to socket.





VID : 4 3 2 1 0

Over current trip level : 90uA(typ.)

Full load Isen current : 90uA/1.5 ~ 60uA

Rds(on) \* Io = Rsen \* Isen

6.5m\*1.5\*20A = Rsen\*60uA

Rsen = 3.25K

OCp : 20A\*1.5\*2 = 60A

Vdroop=Idroop\*R17 ~ Isen\*R17 ~ 72.6mV

If R14 NA, Vdroop=0

ROFS = VOFS\*10/100uA

R18=50mV\*10/100uA = 5K ~ 4.99K

R19 : 107K Ohms -----> f ~ 250K HZ

1.550V : 0 0 0 0 0

1.525V : 0 0 0 0 1

1.500V : 0 0 0 1 0

1.475V : 0 0 0 1 1

1.450V : 0 0 1 0 0

1.425V : 0 0 1 0 1

1.400V : 0 0 1 1 0

1.375V : 0 0 1 1 1

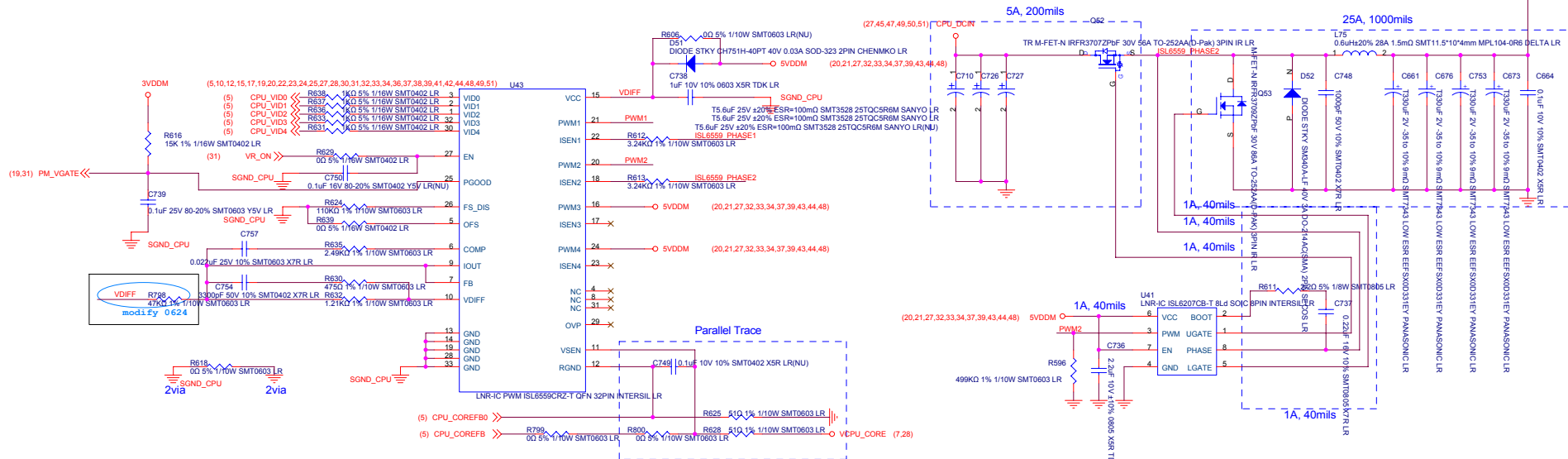
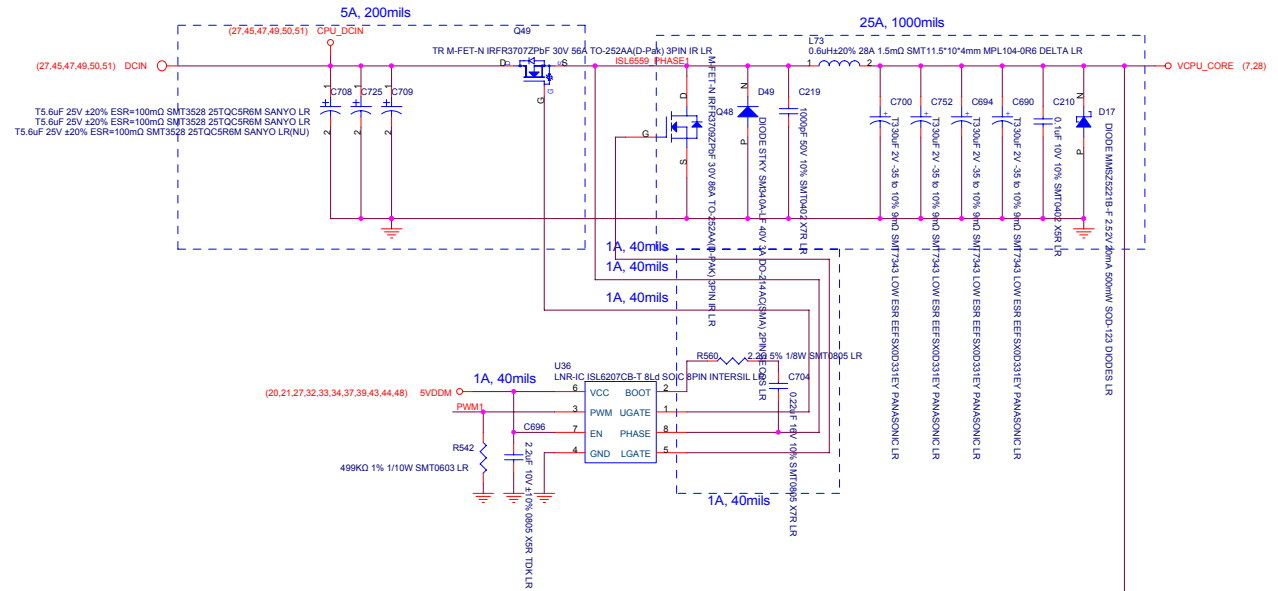
1.350V : 0 1 0 0 0

1.325V : 0 1 0 0 1

1.300V : 0 1 0 1 0

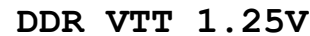
0.800V : 1 1 1 1 0

OFF : 1 1 1 1 1

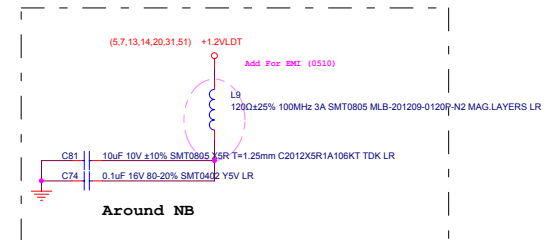




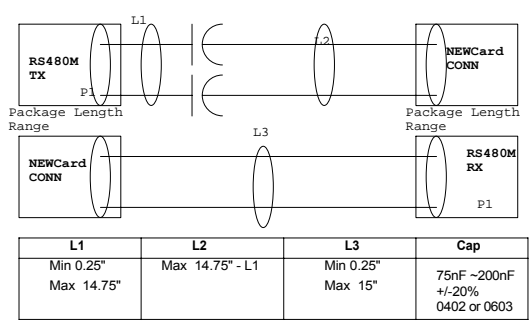
## THERMAL SENSOR/FAN





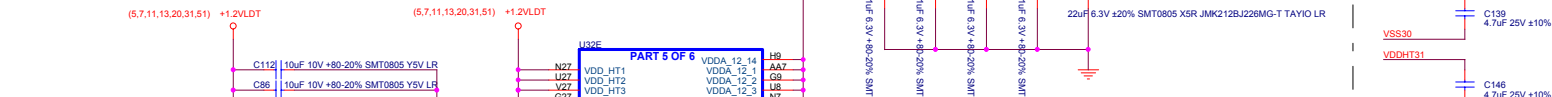






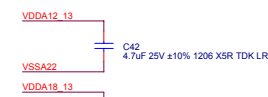
Place all C around Power Plane

The diagram shows a section of a PCB layout. A horizontal power plane is populated with several components. From left to right, there are capacitors C44, C43, C51, C52, and C55. To the right of C55 is an inductor L7 with a value of 1200±25% 100MHz 3A. A red wire connects the right end of the power plane to a red circular pad labeled 1.2VDDM. The coordinates (5,7,11,13,20,31,51) are shown in red above the 1.2VDDM pad.




Place all C around Power Plane

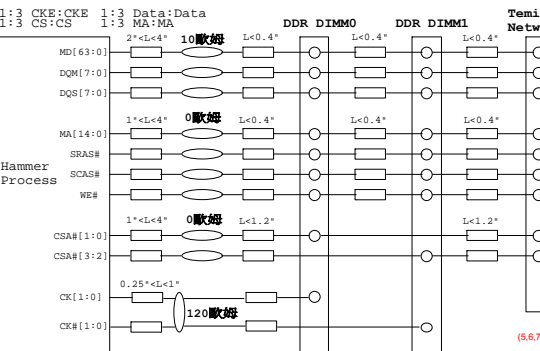
Power Signal	S0	S1	S3	S4/S5	G3
VDDHT	ON	ON	OFF	OFF	OFF
VDDR, VDDRCK	ON	ON	ON	OFF	OFF
VDD18	ON	ON	OFF	OFF	OFF
VDDC	ON	ON	OFF	OFF	OFF
VDDA18	ON	ON	OFF	OFF	OFF
VDDA12	ON	ON	OFF	OFF	OFF
AVDD	ON	ON	OFF	OFF	OFF
AVDDDI	ON	ON	OFF	OFF	OFF
PLLVD	ON	ON	OFF	OFF	OFF
HTPVD	ON	ON	OFF	OFF	OFF
VDDR3	ON	ON	OFF	OFF	OFF
LEVDD	ON	ON	OFF	OFF	OFF
VDDR18D	ON	ON	OFF	OFF	OFF
VDDR18A	ON	ON	OFF	OFF	OFF



VSS89

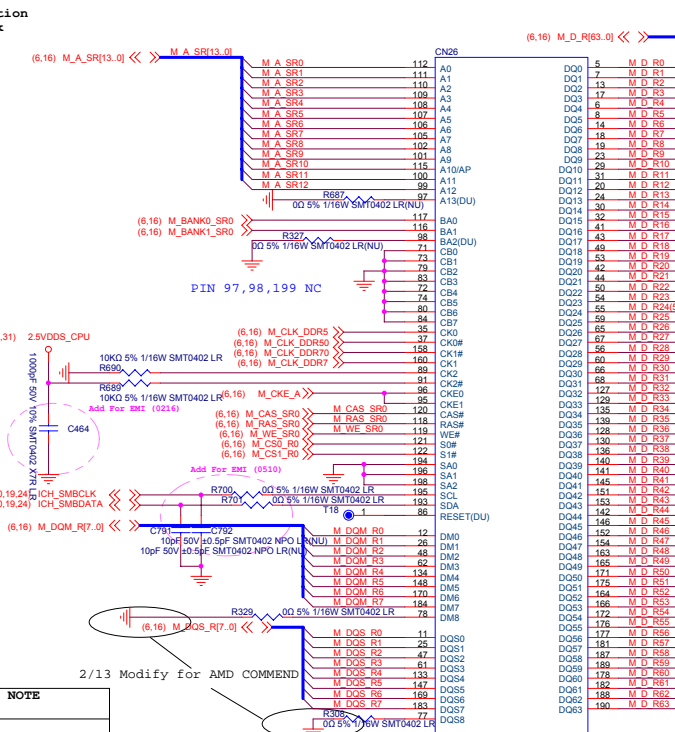
 PUT DECOUPLING CAPS ON THE TOP, CLOSE TO BALLS  
CONNECT VSSA22, VSSA59, VSS30, VSS89 to the ground





SIGNAL GROUP	DATA SIGNALS	STROBE SIGNALS	Length Mismatch
MD Group 0	MD[7:0], DQM0	DQS0	±25mils
MD Group 1	MD[15:8], DQM1	DQS1	±25mils
MD Group 2	MD[23:16], DQM2	DQS2	±25mils
MD Group 3	MD[31:24], DQM3	DQS3	±25mils
MD Group 4	MD[39:32], DQM4	DQS4	±25mils
MD Group 5	MD[47:40], DQM5	DQS5	±25mils
MD Group 6	MD[55:48], DQM6	DQS6	±25mils
MD Group 7	MD[63:56], DQM7	DQS7	±25mils
MA(& Control)	MA[14:0], CAS#, RAS#, WE#		
CS(Chip Select)	CSA#[5:0]		
CKE	CKE#[5:0]		
Clocks	FWDSDCLKOUT, DDRCLK[8:0]/DDRCLK#[8:0], FB_OUT/FB_OUT#		

SIGNAL GROUP	WIDTH:SPACE	TRACE LENGTH	TRACE LENGTH MATCHING	NOTE
MD Group[7:0]	1:3 Data:Strobe 1:3 Data:Other 1:4 M_DQS:Other	1"<L1<3.5" (Avg=3")	<100mil mismatch within group. <2 inch mismatch between group.	
MA(& Control)	1:3 MA:MA 1:3 MA:Other	1"<L<4"		
CS(Chip Select)	1:3 CS:Other	1"<L<4"		
CKE	1:3 CKE:Other	14"<L<20" L<2<2"		
Clocks	1:1 CLK:CLK# 1:3 CLK#:Other	L2=6" L3=4" L4=L2+L3-Avg(L1)+5.6"		



M\_CS0\_R0  
M\_CS1\_R0  
M\_CS2\_R0  
M\_CS3\_R0  
M\_CKE0\_R0  
M\_CKE1\_R0  
M\_CKE2\_R0  
M\_CKE3\_R0

1.25VDD5

68 ohm 5%

Claw Hammer

L1

Min=0.5"

Max=5.0"

L2

Max=2.0"

SO-DIMM PAD

Claw Hammer

M\_A\_FR[12..0]  
M\_RAS\_FR0  
M\_CAS\_FR0  
M\_WE\_FR0  
M\_BS0\_FR0  
M\_BS1\_FR0

M\_A\_SR[12..0]  
M\_RAS\_SR0  
M\_CAS\_SR0  
M\_WE\_SR0  
M\_BS0\_SR0  
M\_BS1\_SR0

1.25VDD

10 ohm 5%  
47 ohm 5%

L1 L2 L3 L4

Min=1.0"  
Max=4.0"

Max=1.1"  
Max=0.2"  
Max=0.8"

SO-DIMM0 PAD SO-DIMM1 PAD

Note : Connect to the MCH-M SMA[12..0] pins  
Connect to SO-DIMM1 with a 10 ohm +/-5% resistor

1.25V DDDS

M\_D[63..0]  
M\_DQS[7..0]  
M\_DQM[7..0]

RS: 10 ohm 5%

Claw Hammer

L1=1-3.5"  
L2=0.5-1"

L3=0.4"  
~0.8"

SO-DIMM0 PAD SO-DIMM1 PAD

RTT: 68 ohm 5%

L4=0.20-0.5"

M\_D\_R[63..0]  
M\_DQS\_R[7..0]  
M\_DQM\_R[7..0]

Note: L1+L2 = 1.50-5.00" in length to DIMM0  
L2 as short as possible, must be <=1.0"

Claw Hammer

Min=0.25"

Max=1.0"

120 ohm 5%

ETT

L1

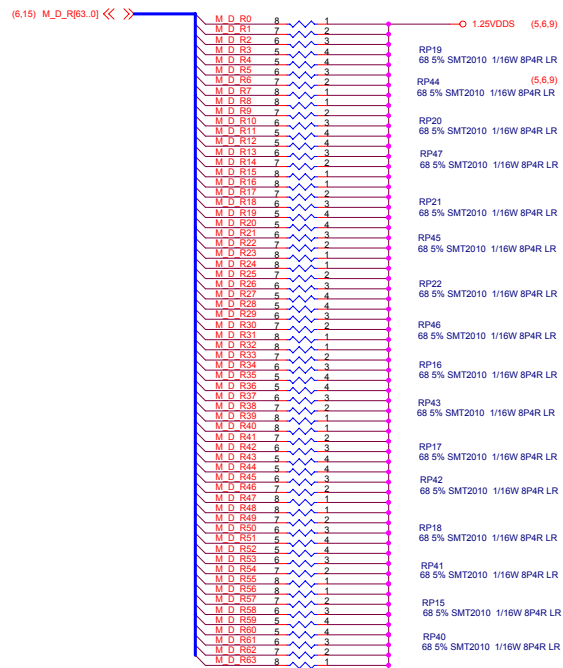
L2

M\_MEMCLK\_H/L[7..0]

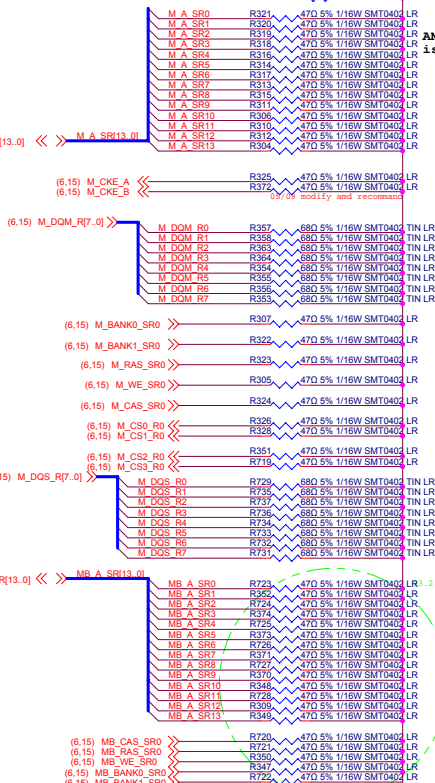
SO-DIMM0 PAD

SO-DIMM0 PAD

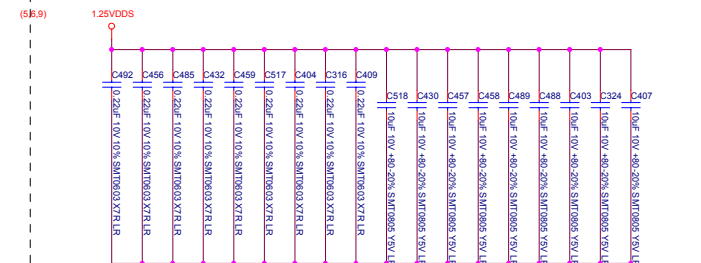
L1+L2  
=1.5"~5.0"



AMD order #24665  
is revised

[illegible]

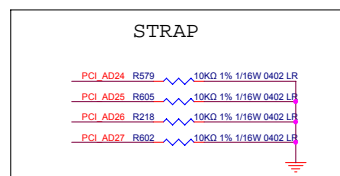
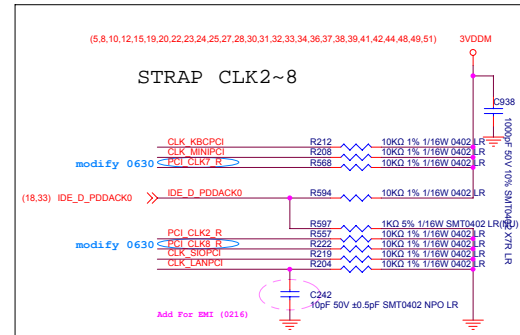
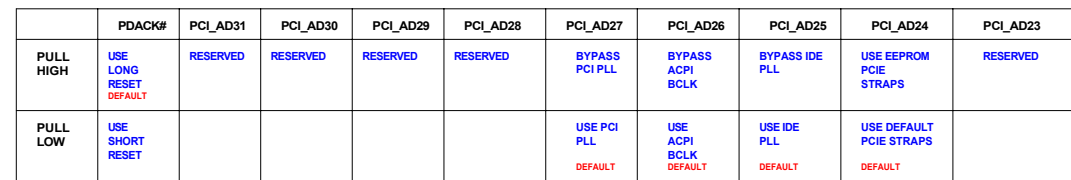
0415 MODIFY



**LAYOUT: Add 100pF and 1000pF 1.25VDD5 fill near Clawhammer and near DIMMs (Both Sides)**

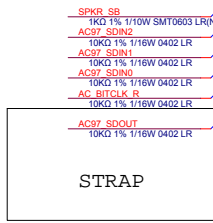
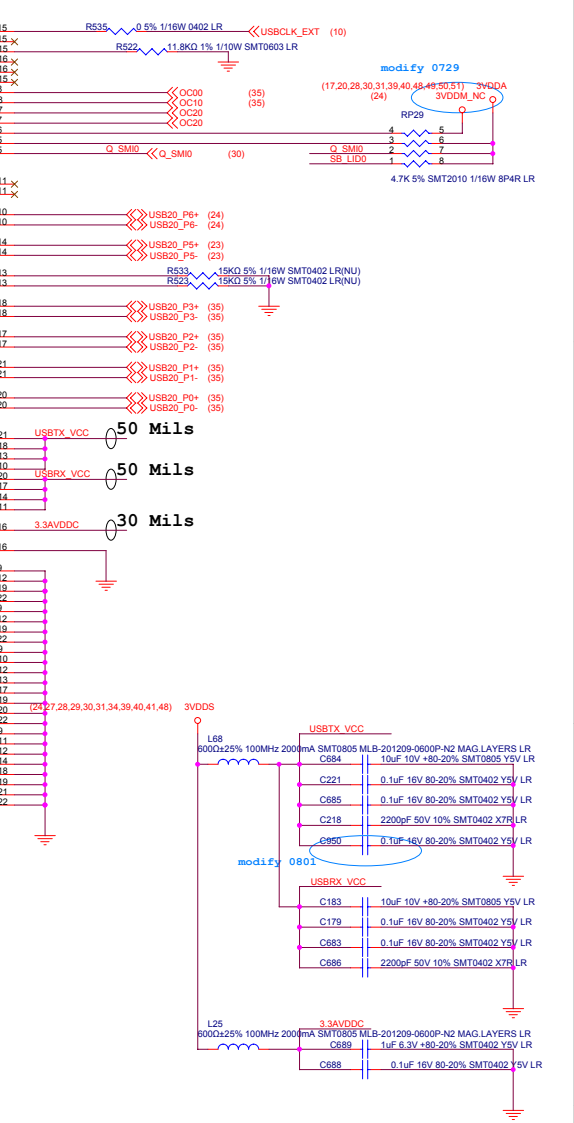
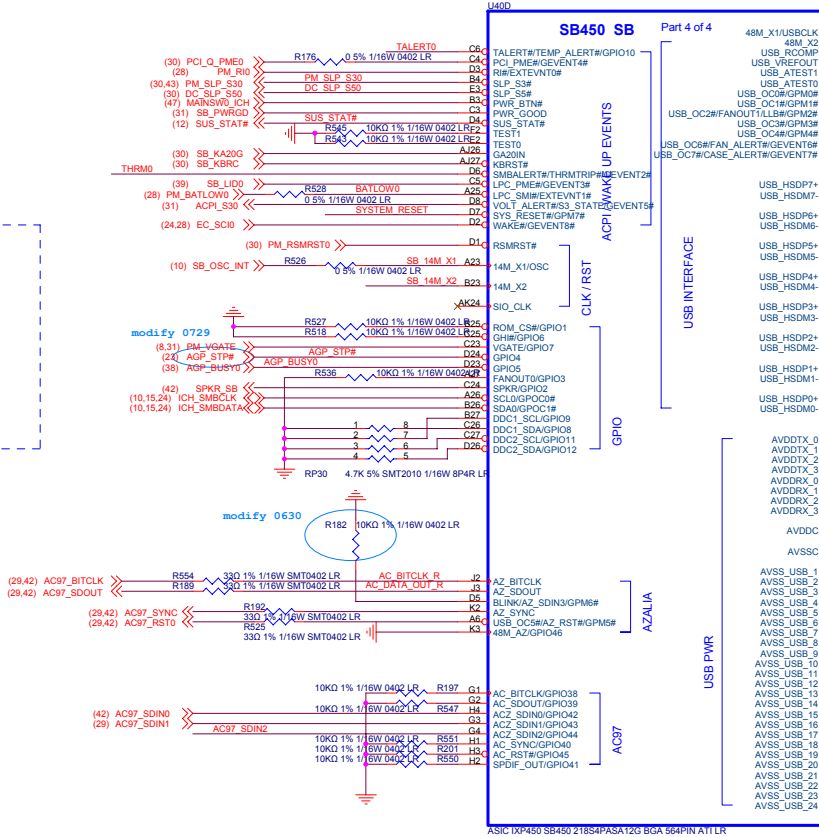
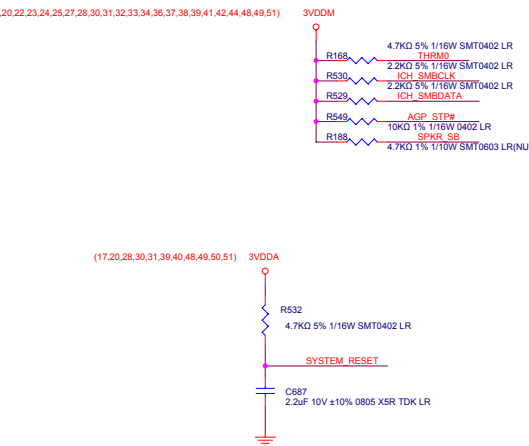
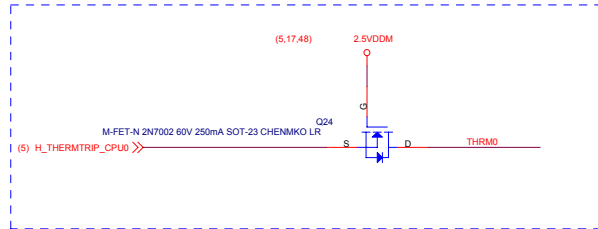
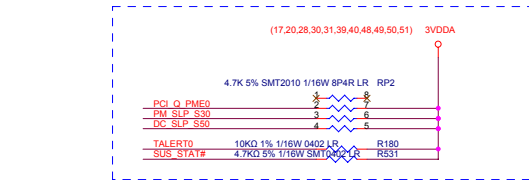
**Place on backside, evenly spaced around VTT fill.**

**LAYOUT: RTT 120  $\Omega$  near to process.**  
Min=0.25" Max= 1.0"

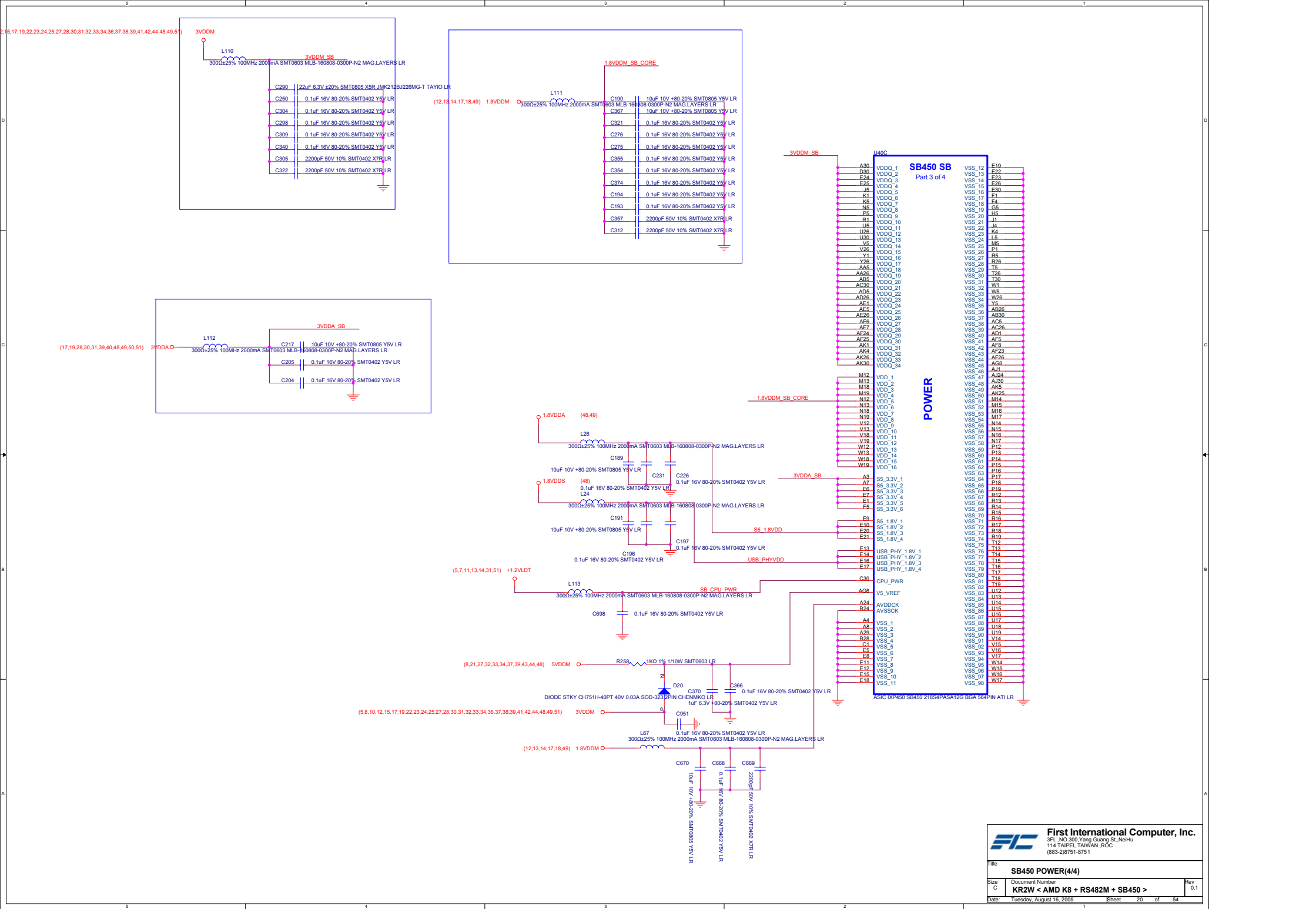


	ACPWRON	AC_SDOUT	RTC_CLK	SPDIF_OUT	PCI_CLK2	PCI_CLK3	PCI_CLK4	PCI_CLK5	PCI_CLK6	PCI_CLK7	PCI_CLK8
PULL HIGH	MANUAL PWR ON	USE DEBUG STRAPS	INTERNAL RTC	SIO 24MHz	48MHz XTAL MODE	USB PHY PWRDOWN DISABLE	USE INT. PLL48	14MHz OSC MODE	CPU IF = K8	ROM TYPE H,H = PCI ROM L,L = PMC LPC ROM	
	DEFAULT		DEFAULT		DEFAULT	DEFAULT	DEFAULT	DEFAULT	DEFAULT		
PULL LOW	AUTO PWR ON	IGNORE DEBUG STRAPS	EXTERNAL RTC (NOT SUPPORTED W/ I78712)	SIO 48MHz	48MHz OSC MODE	USB PHY PWRDOWN ENABLE	USE EXT. 48MHz	14MHz XTAL MODE	CPU IF = P4	L,H = NORMAL LPC ROM L,L = FWH ROM	DEFAULT







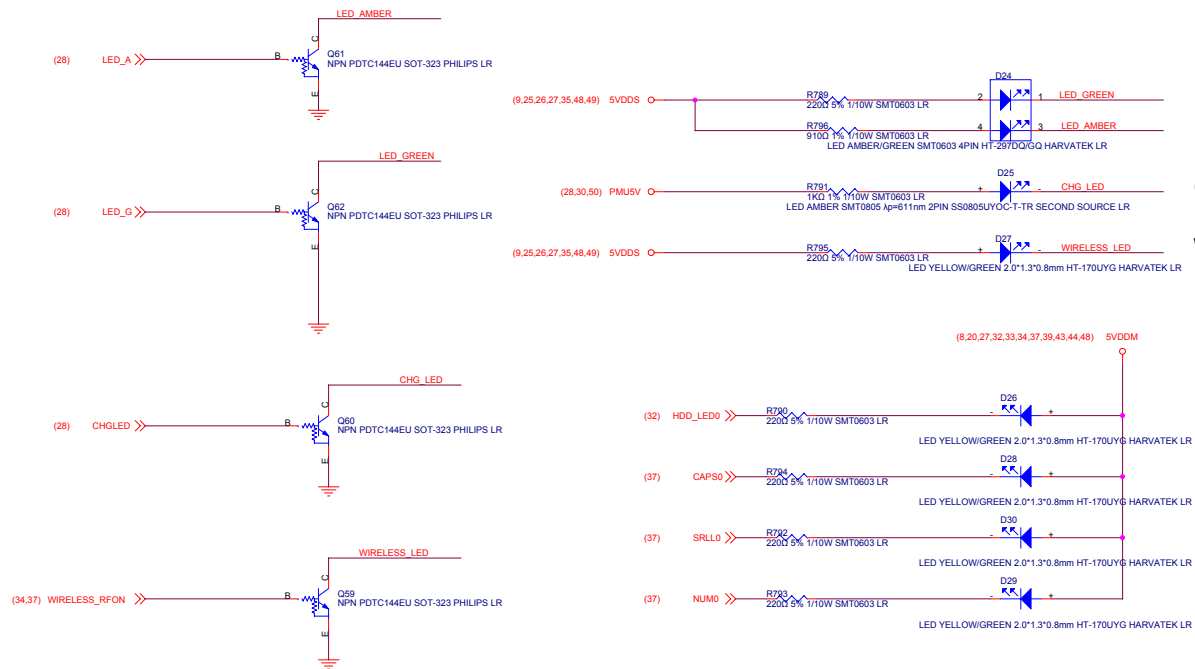




## Switch



### LED indicator control logic

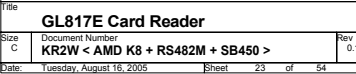


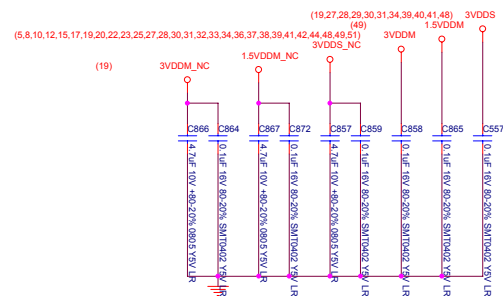
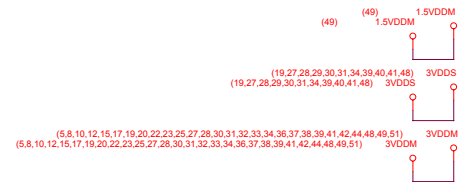
### Power indicator

### Charge indicator

### Wireless indicator







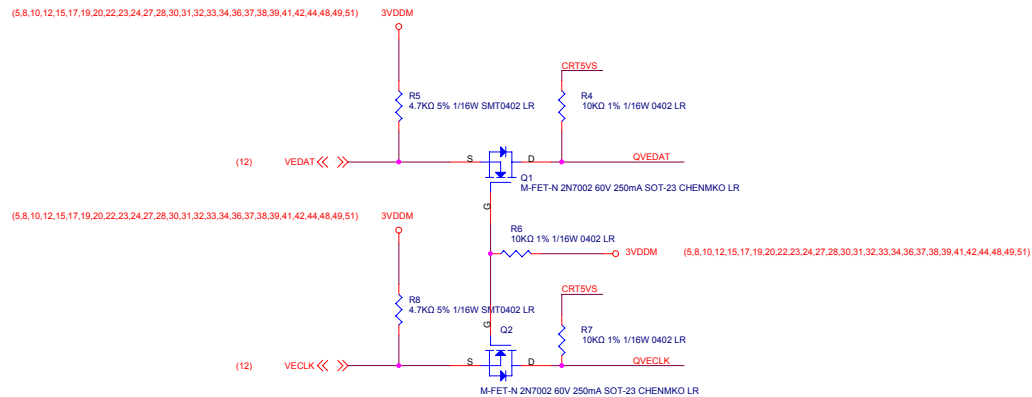
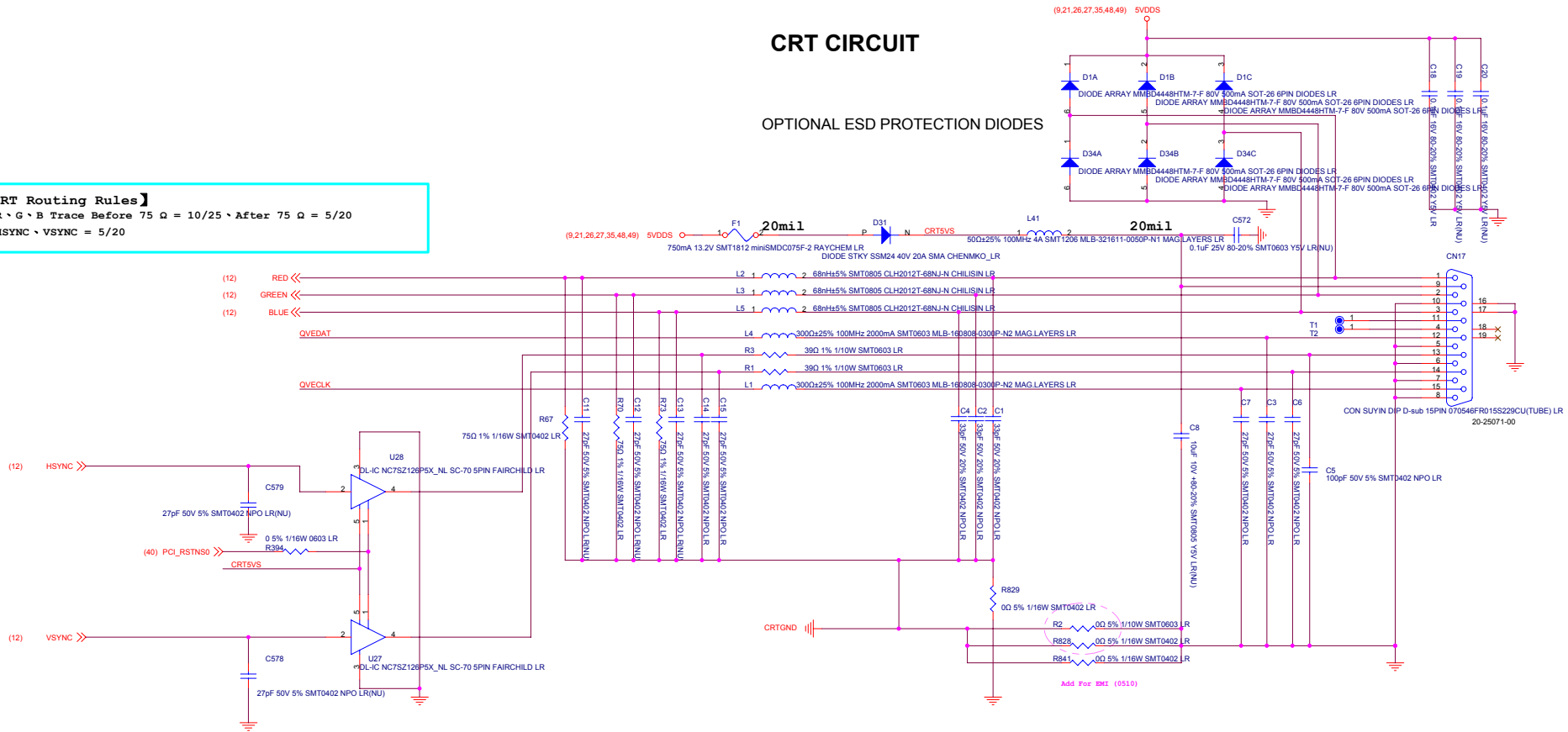
RSVD for EMI

# CRT CIRCUIT

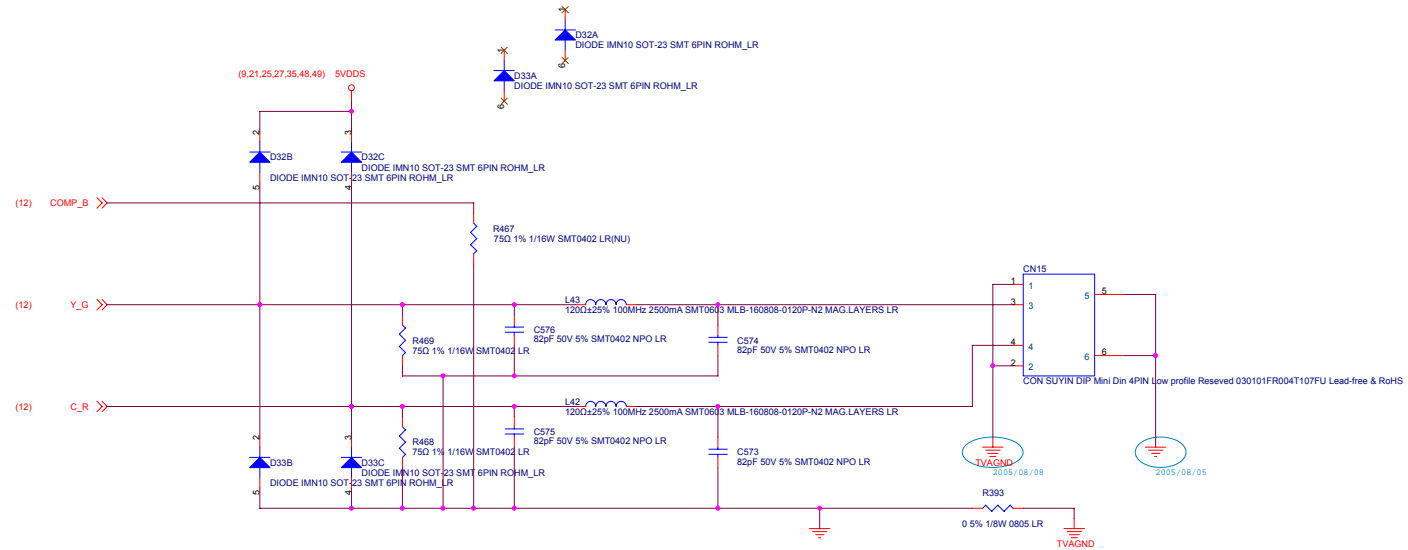
## OPTIONAL ESD PROTECTION DIODES

### 【CRT Routing Rules】

1. R、G、B Trace Before 75  $\Omega$  = 10/25、After 75  $\Omega$  = 5/20
2. HSYNC、VSYNC = 5/20



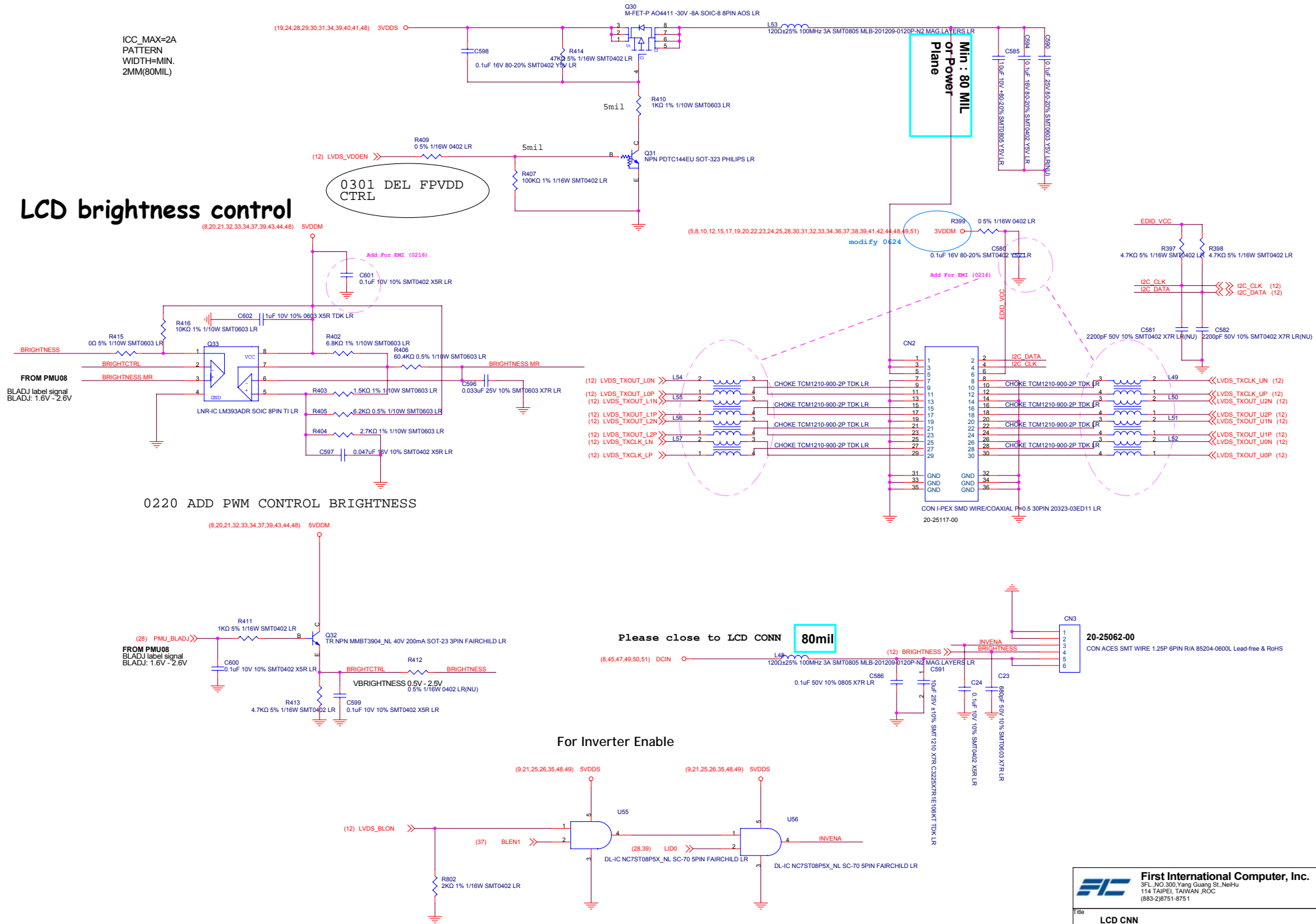
## TV OUT CIRCUIT





ICC\_MAX=2A  
PATTERN  
WIDTH=MIN.  
2MM(80MIL)

## LCD brightness control



CLOSE TO PIN 1 OF PMU08

ATTENTION

IT IS POSSIBLE TO CUT THE PATTERN OF PIN78 AND PIN79

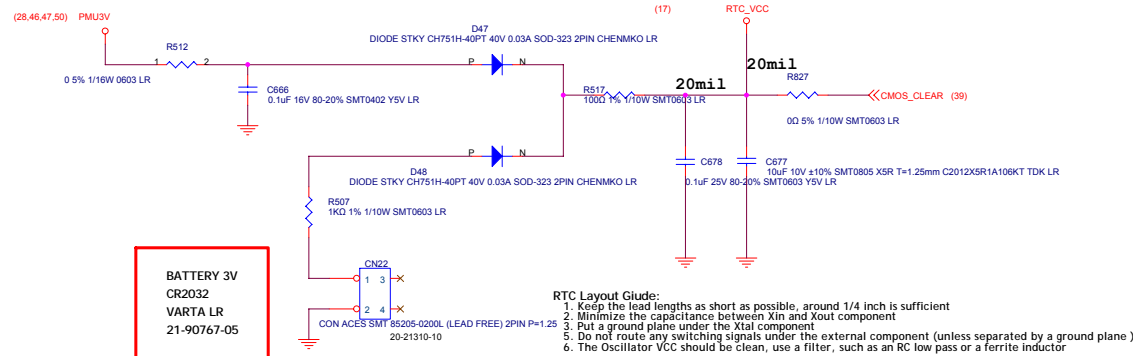
GPIOA0-A7-----INPUT  
GPIOB0-B6-----INPUT  
GPIOB7-----OUTPUT  
GPIOC0-C2-----INPUT  
GPIOC2-C3-----OUTPUT

MAIN BATTERY VOLTAGE SENSE  
Close to PMU08

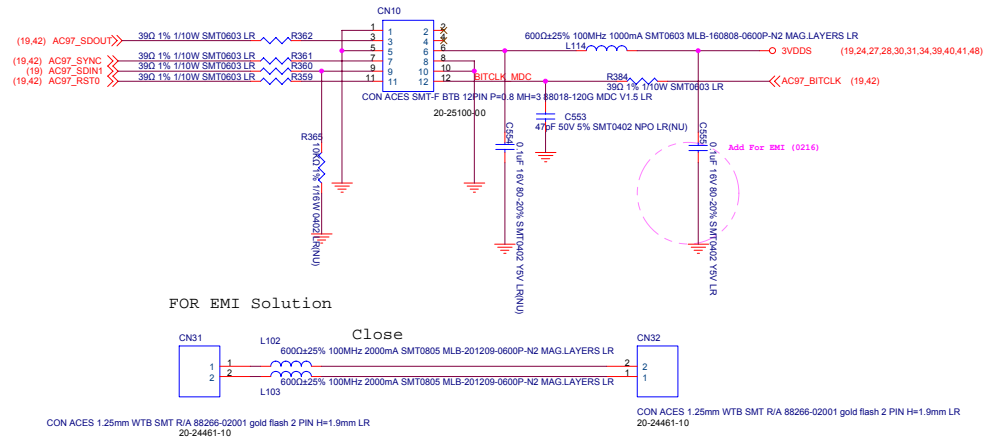
First International Computer, Inc.  
3FL NO.303, Yang Guangyuan St., Neihu  
114 TAIPEI, TAIWAN, R.O.C.  
(886-2)8751-8751

File	PMU08	Rev	0.1
Size	Document Number		
C	KR2W < AMD K8 + RS482M + SB450 >		
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## RTC Discharge Circuit

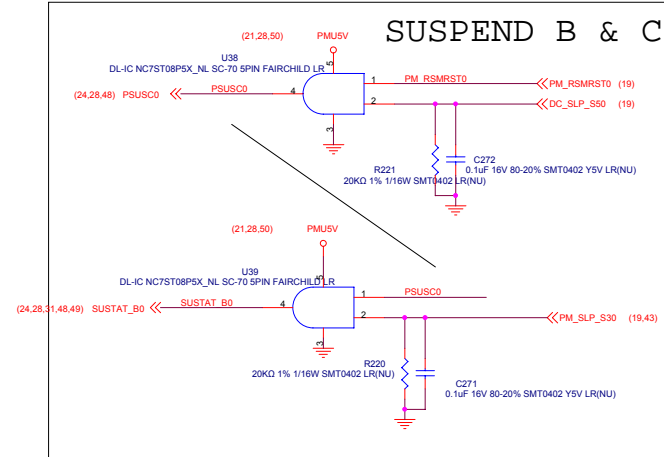
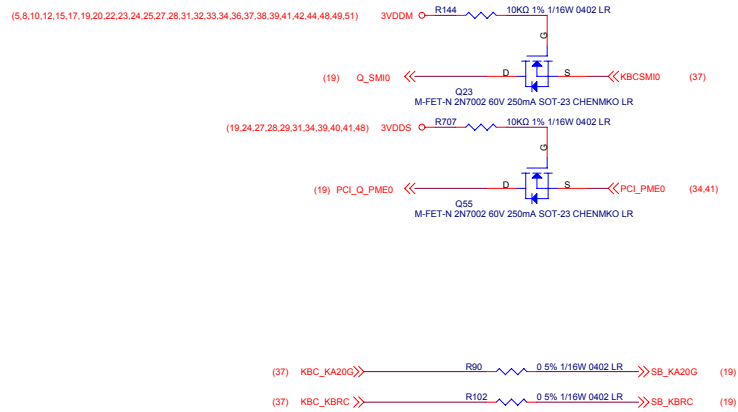


## MDC CNN

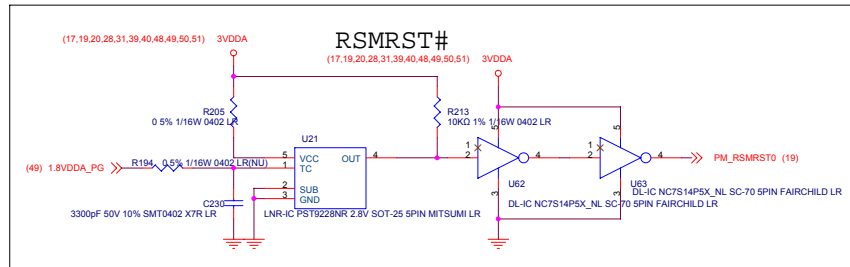


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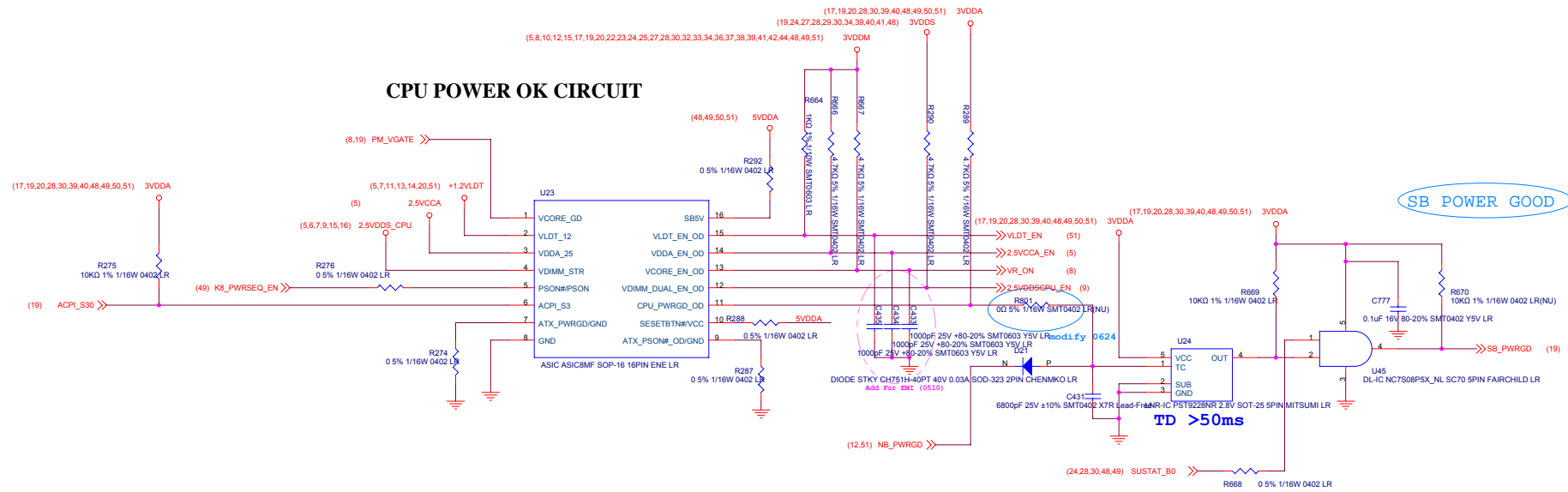
File	RTC/ MDC CNN		
Size	Document Number	Rev	
C	KR2W < AMD K8 + RS482M + SB450 >	0.1	
Date	Tuesday, August 16, 2005	Sheet	29 of 54



## RESUME RESET



## CPU POWER OK CIRCUIT



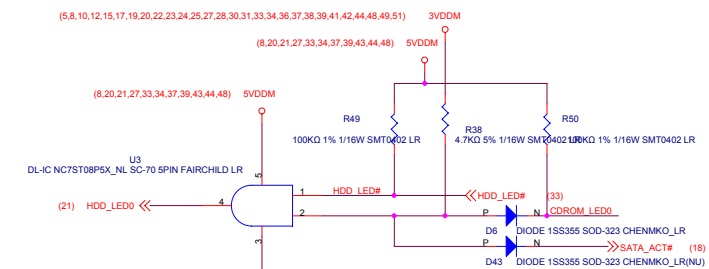
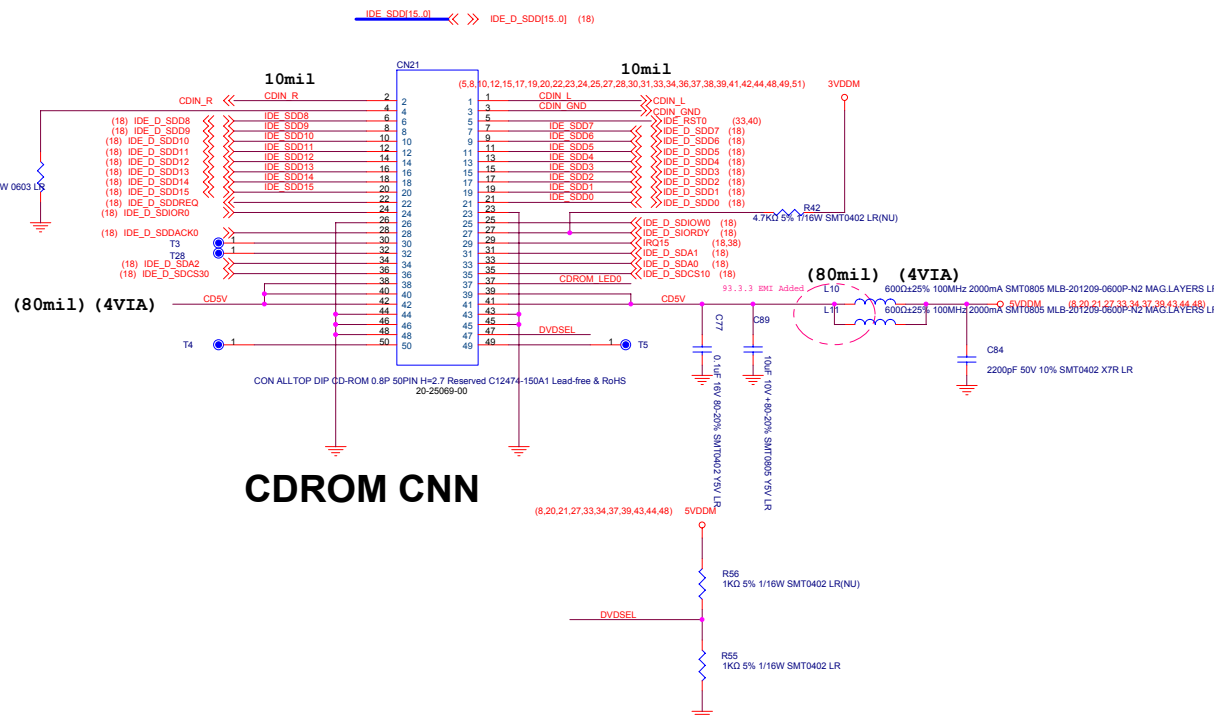
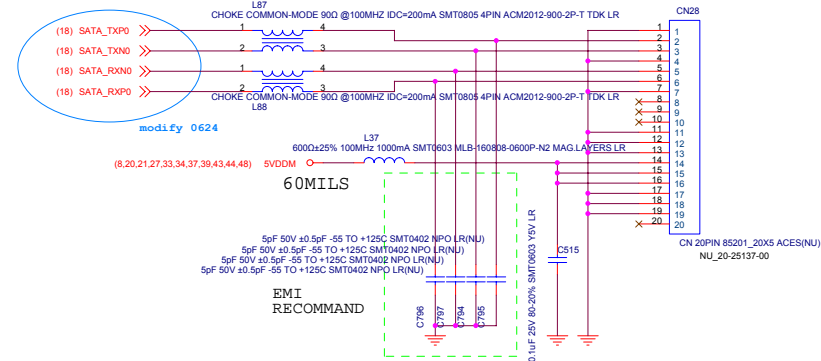
SATA differential stripline	20:4:8:4:20
SATA differential microstripline	20:5:8:5:20
請包GROUND	

MS or SL:

TX

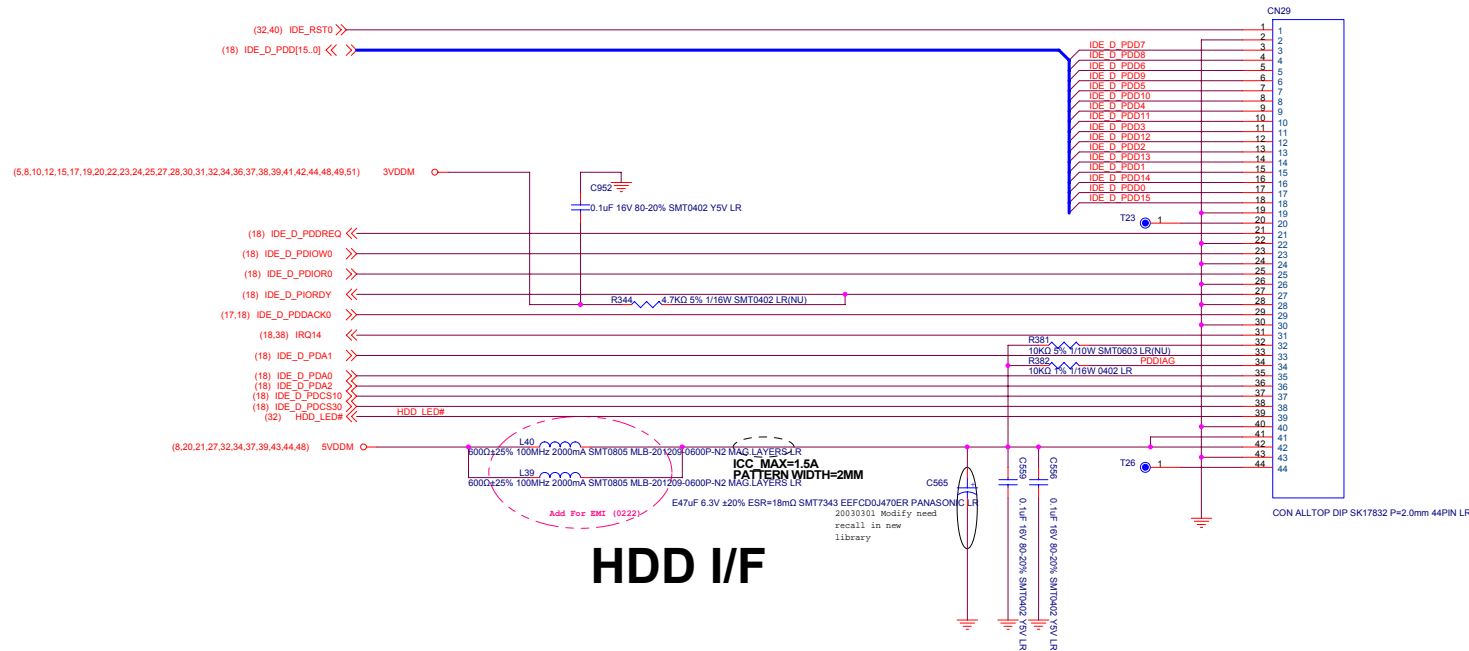
RX

- \* Zdif = 100 Ohm +/- 10%. TX & RX should refer GND.No via & stubs. The Best layer is Top.
- \* TX/RX trace length < 2 inchs.
- \* TX+/- need matching trace  $\pm 10$  mils length.
- \* RX+/- need matching trace  $\pm 10$  mils length.
- \* SATA Pair to Pair Trace matching trace  $\pm 10$  mils length.





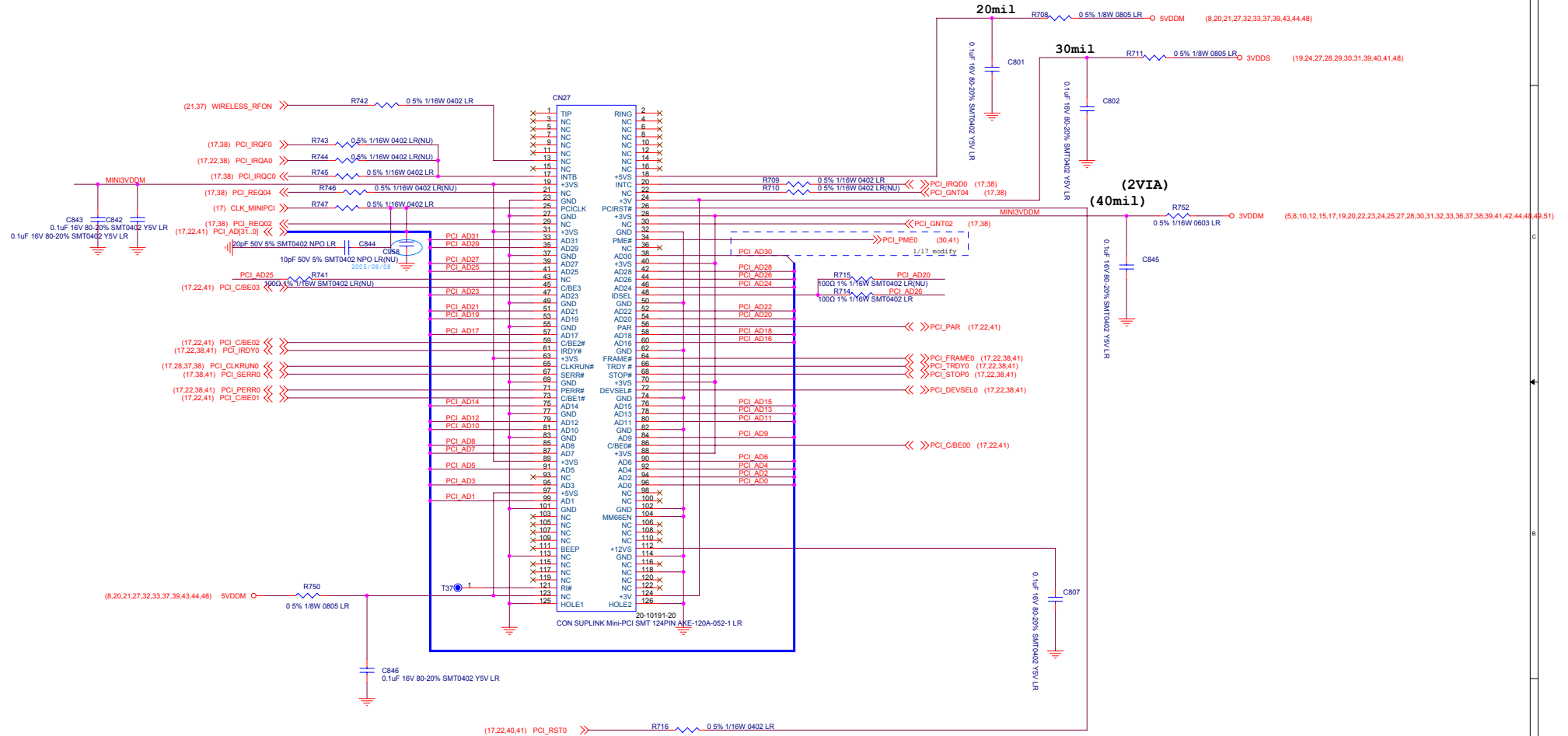
## HDD I/F



**IDE Signals** (microstrip)

Signals	MAX Length (inch)	Width (mils)	Space (mils)
IDE_PDD[15:0]	8	5	7
IDE_SDD[15:0]	8	5	7
IDE_PDA0-2	8	5	7
IDE_SDA0-2	8	5	7
IDE_PDCS 10-30#	8	5	7
IDE_PDDREQ	8	5	7
IDE_SDDREQ	8	5	7
IDE_PDIOW#	8	5	7
IDE_PATADET	8	5	7
IDE_SATADET	8	5	7
IDE_FDDACK#	8	5	7
IDE_SDDACK#	8	5	7

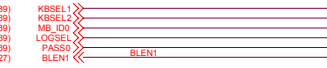
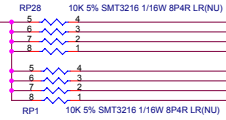
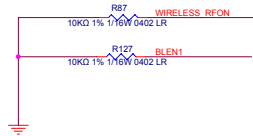
# TYPE III MODEM / LAN CONNECTOR



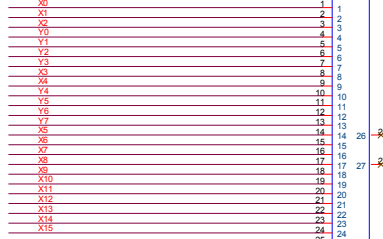




(5,8,10,12,15,17,19,20,22,23,24,25,27,28,30,31,32,33,34,36,38,39,41,42,44,48,49,51)



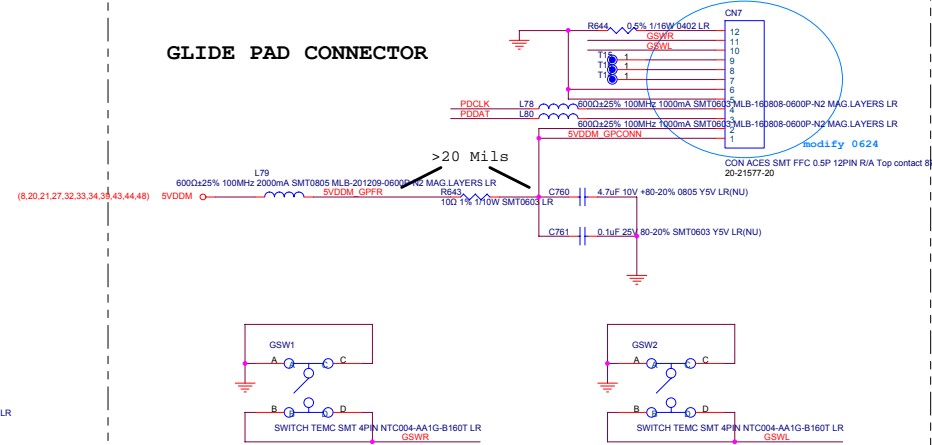
### INT KB CNN



CON ACES SMT FPC P=1.0 85202-25061 H=2 LR

20-25101-00

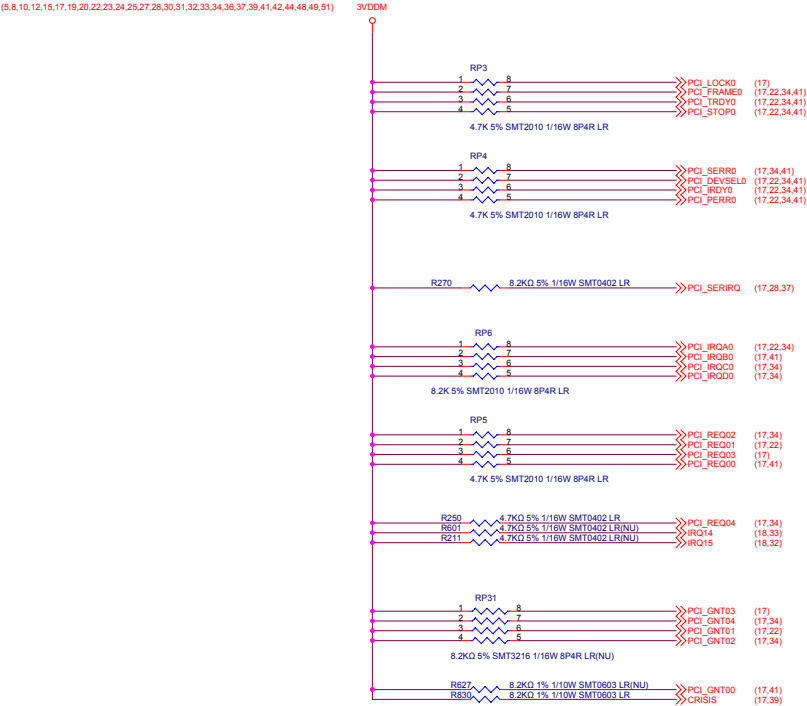
### GLIDE PAD CONNECTOR



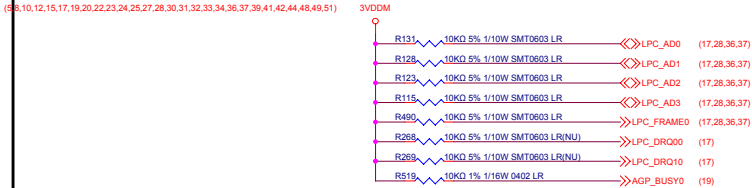
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3FL NO 300, Yang Guang St. Neihu  
114 TAIPEI, TAIWAN ROC  
(885-2)8751-8751

Title		LPC KBC (M3886)	
Size		Document Number	
C		KR2W < AMD K8 + RS482M + SB450 >	
Date		Tuesday, August 18, 2005	
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Rev		0.1	

PCI Pull Up/Down



LPC Pull Up

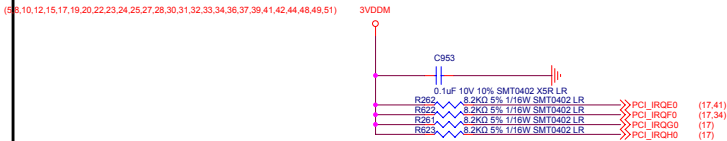


PCI PMU Pull Up

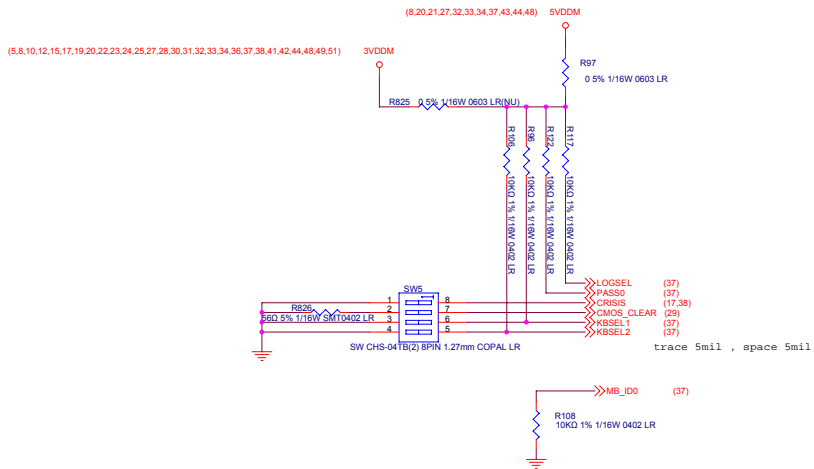
PME PULL HI 3VDDA



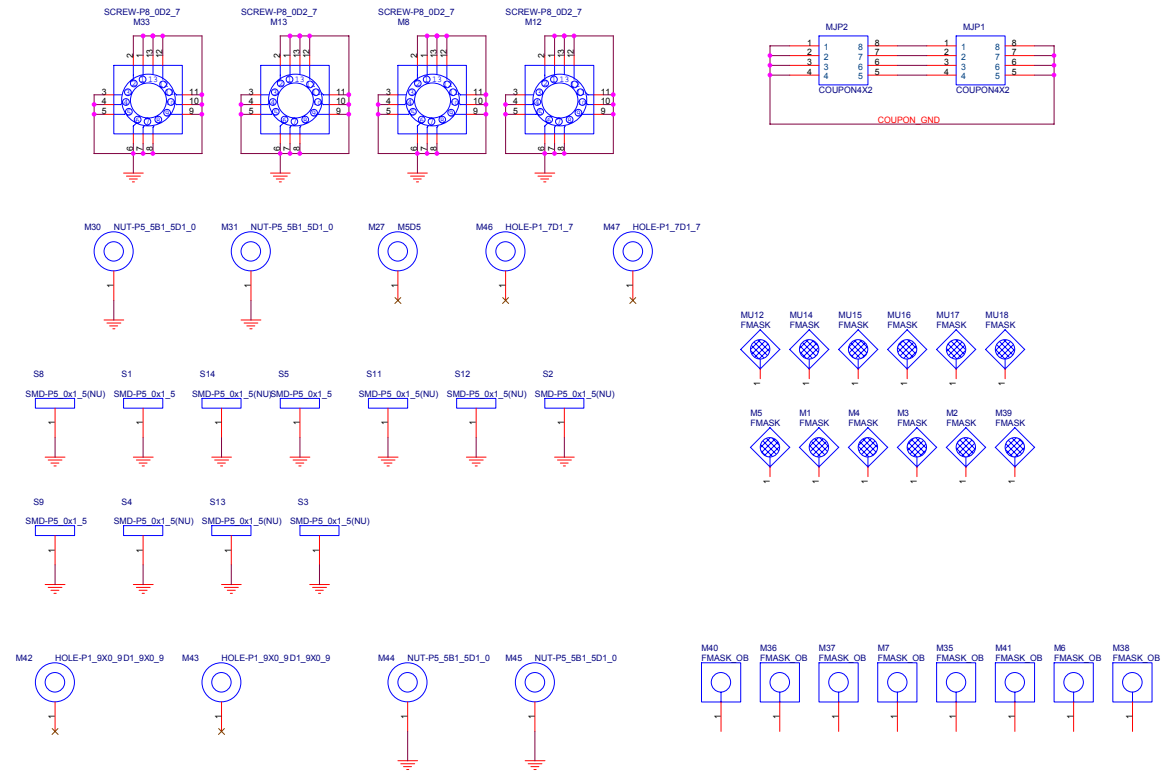
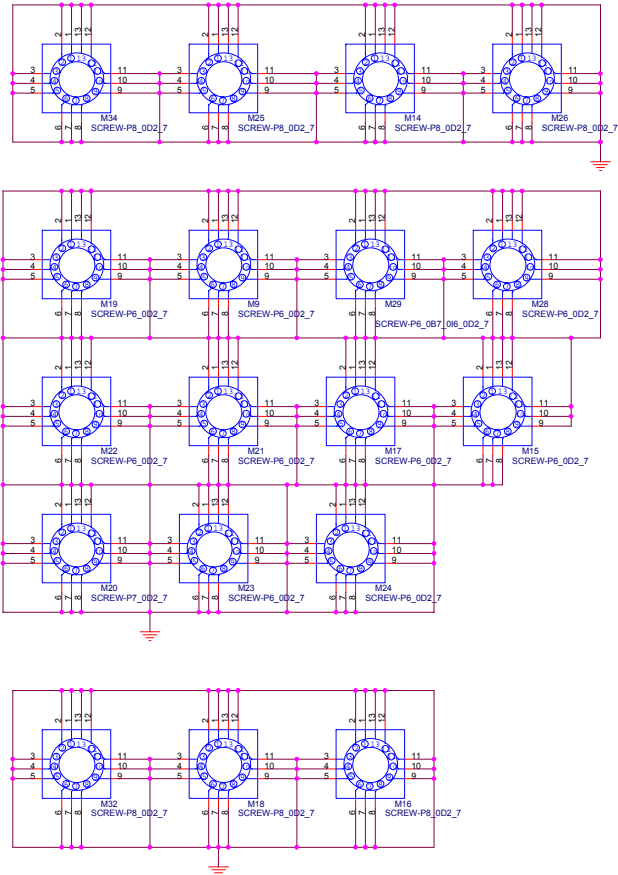
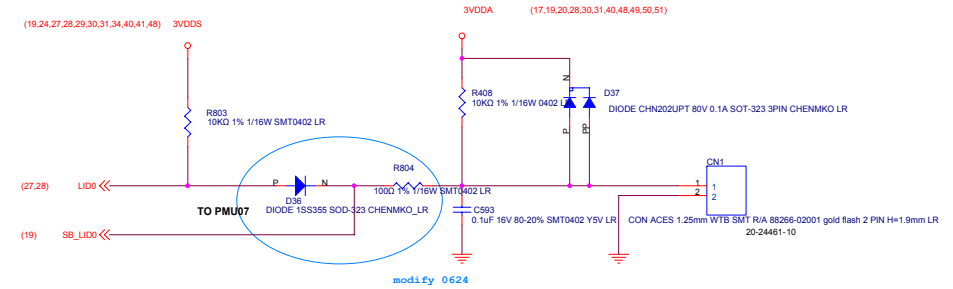
GPIO Pull Up



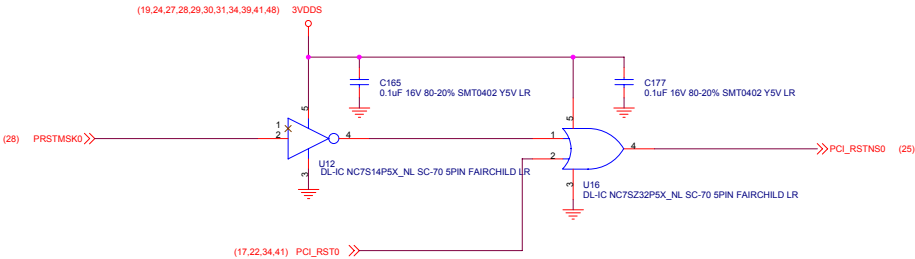
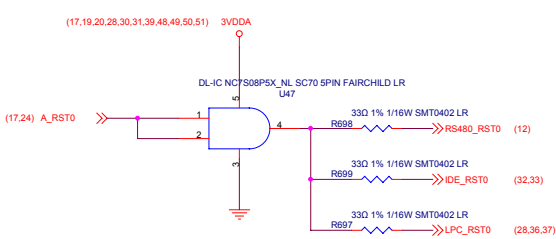
## DIP SWITCH



## LID Switch



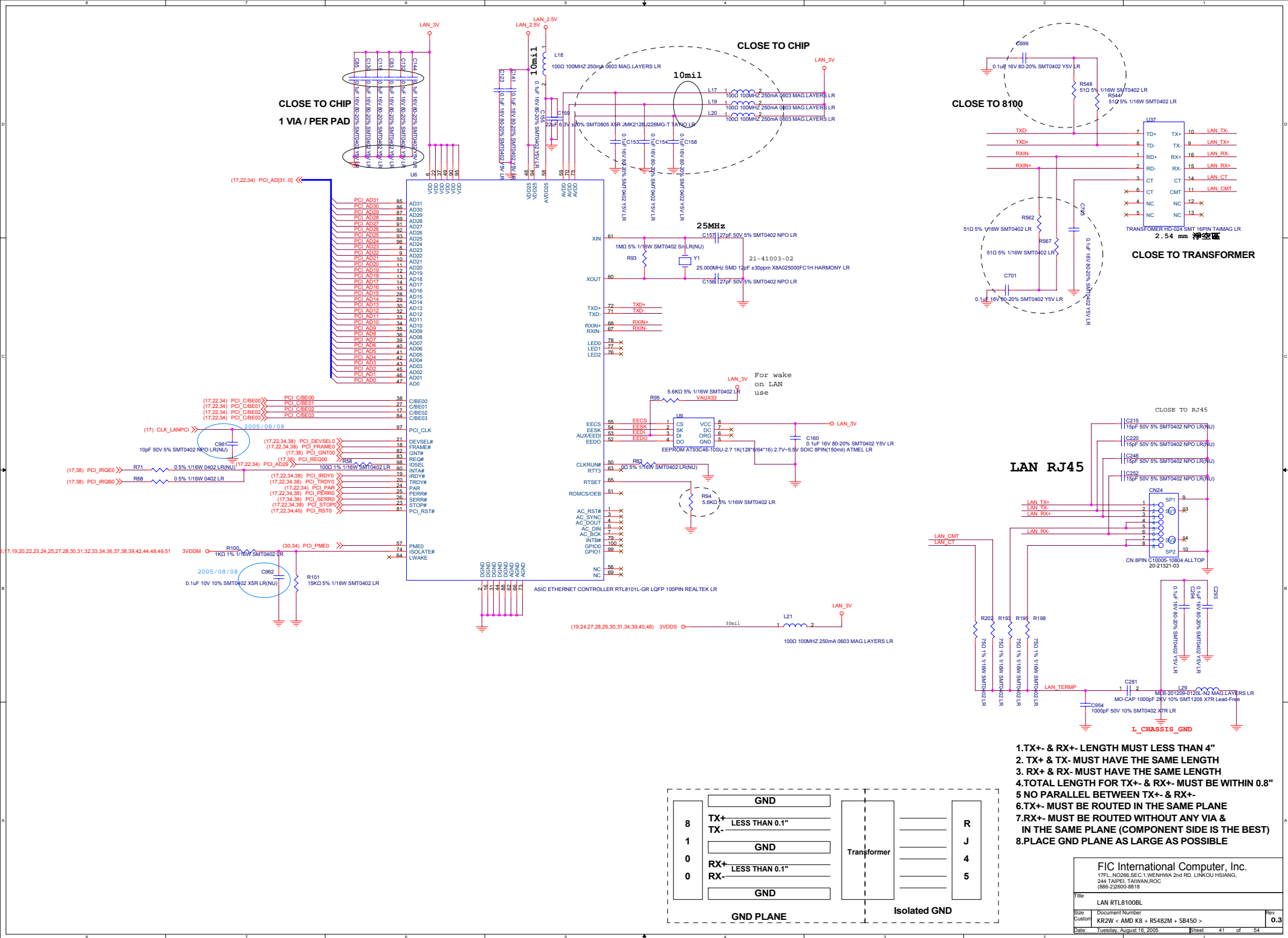
PCI RESET & PCI NON RESET

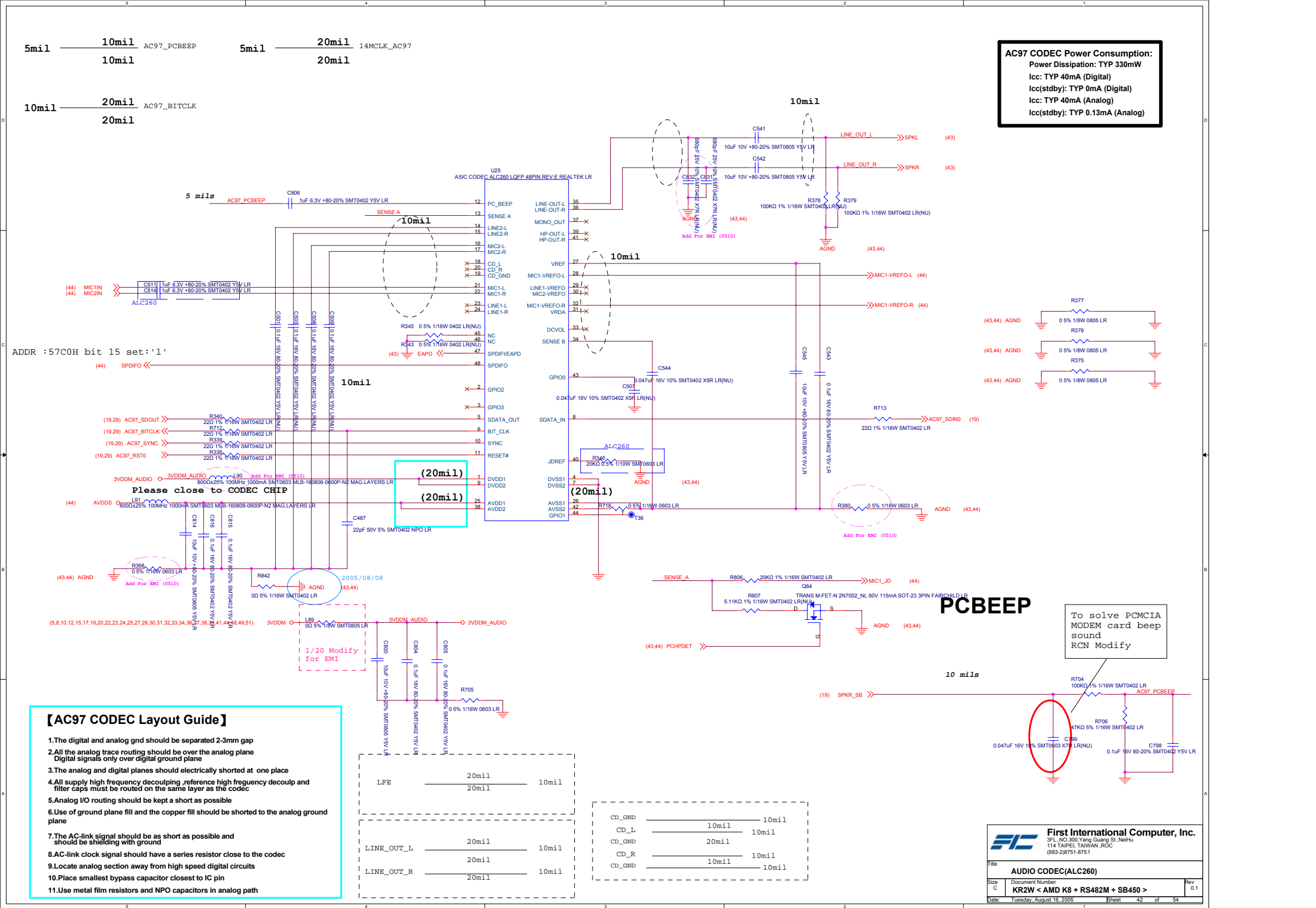


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Title				PCI/IDE Reset Circuit			
Size		Document Number			Rev		
C		KR2W < AMD K8 + RS482M + SB450 >			0.1		
Date:		Tuesday, August 16, 2005		Sheet		40 of 54	



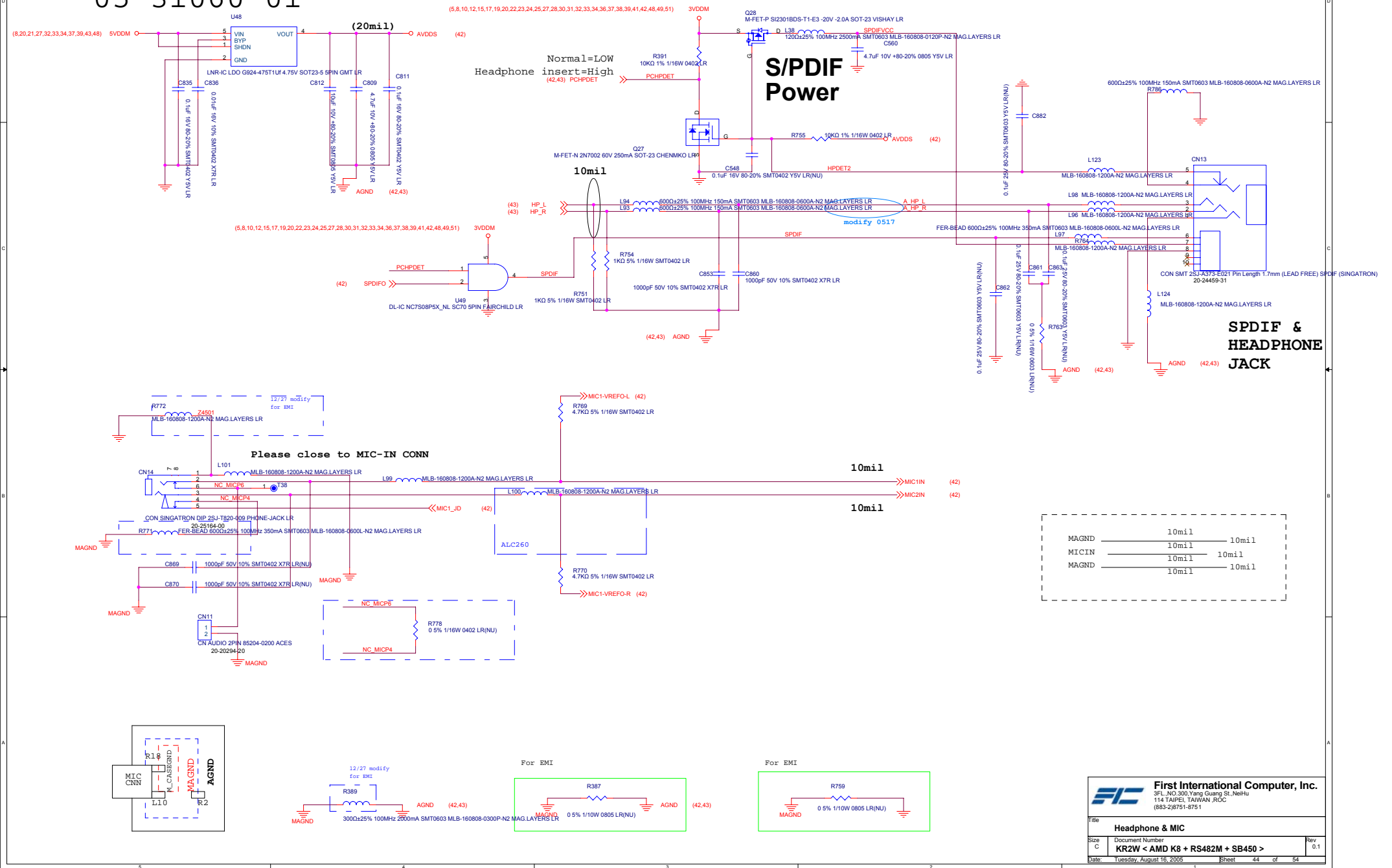


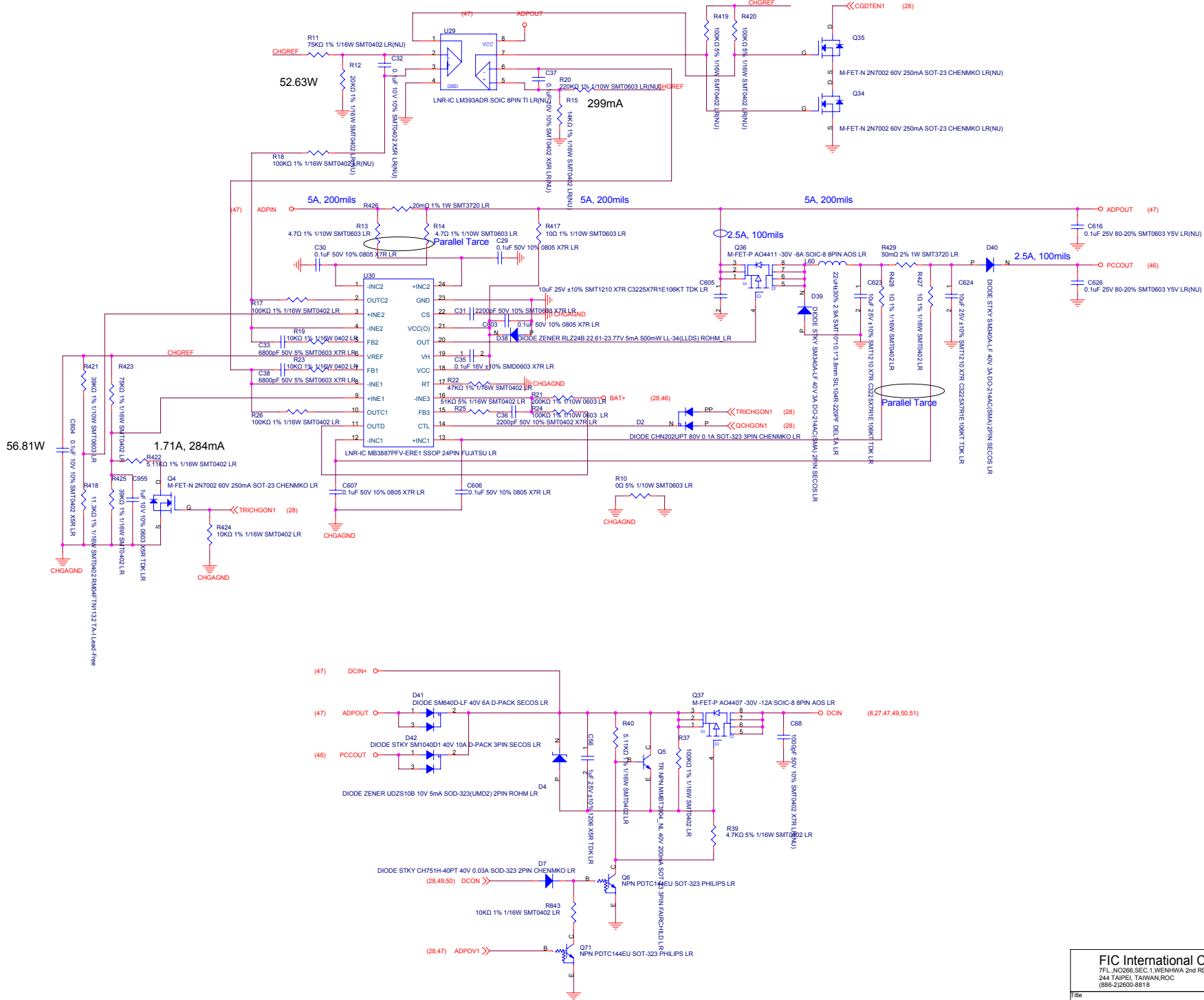




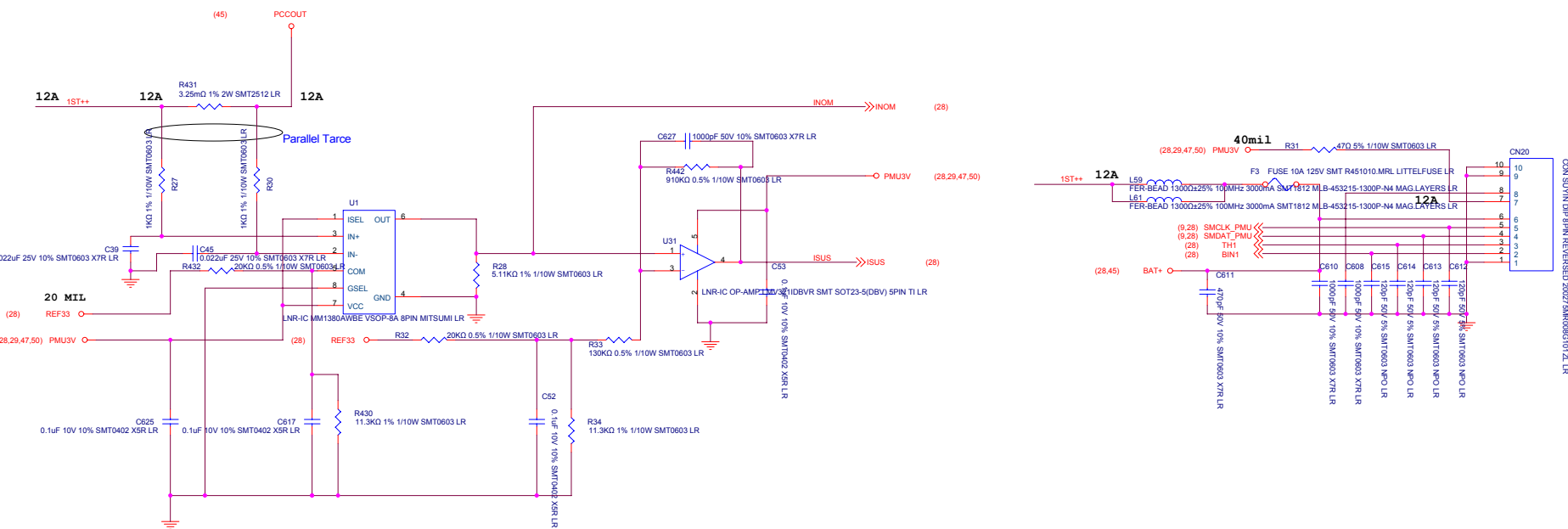
Title			
AUDIO AMP & SPEAKER			
Size	Document Number	Rev	
C	KR2W < AMD K8 + RS482M + SB450 >		
Date:	Tuesday, August 16, 2005	Sheet	43 of 54

# 05-31060-01



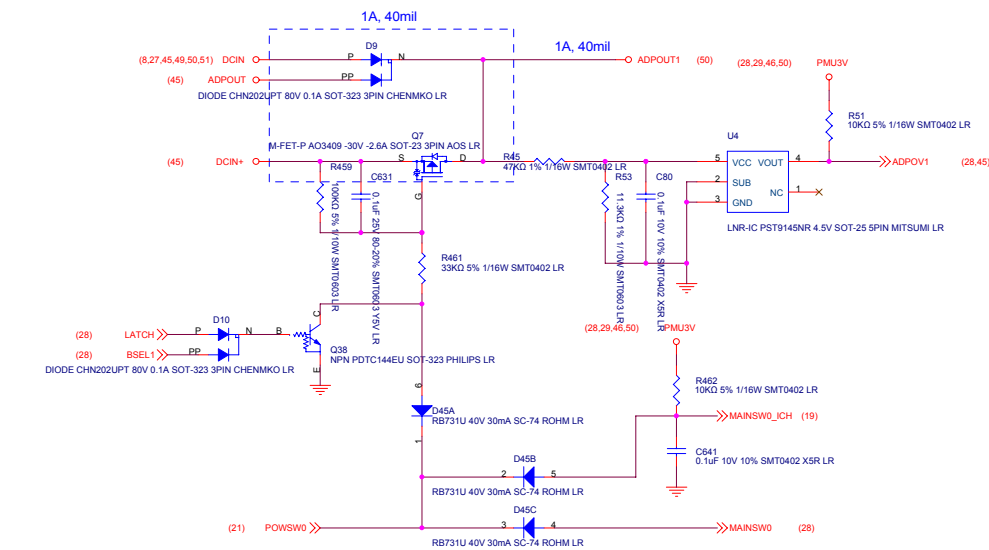


CHR Board BATTERY IN

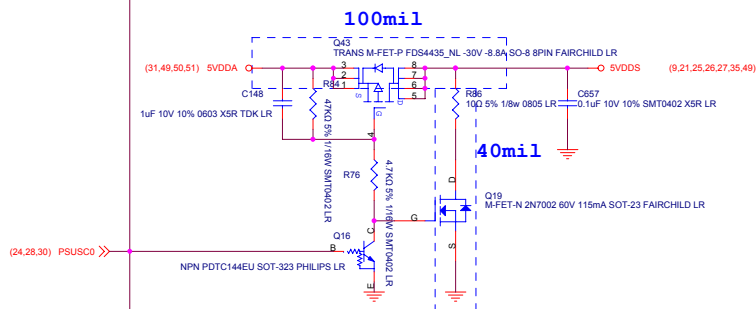
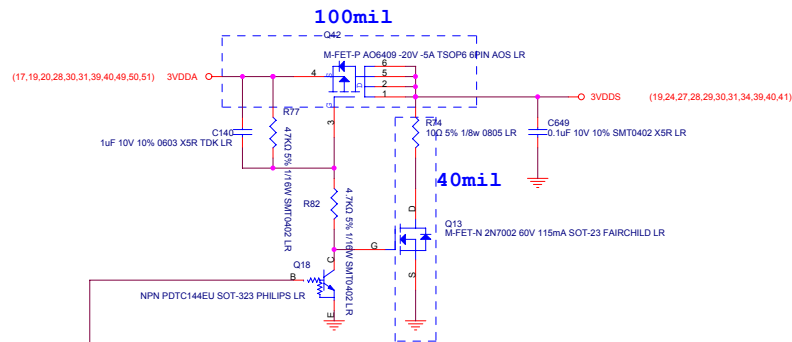


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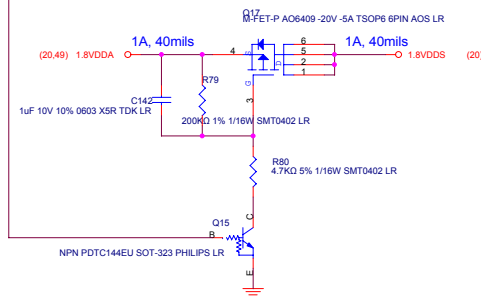
File				<b>Battery Voltage Sense</b>			
Size		Document Number				Rev	
C		KR2W < AMD K8 + RS482M + SB450 >				0.	
Date:		Tuesday, August 16, 2005		Sheet		46 of 54	



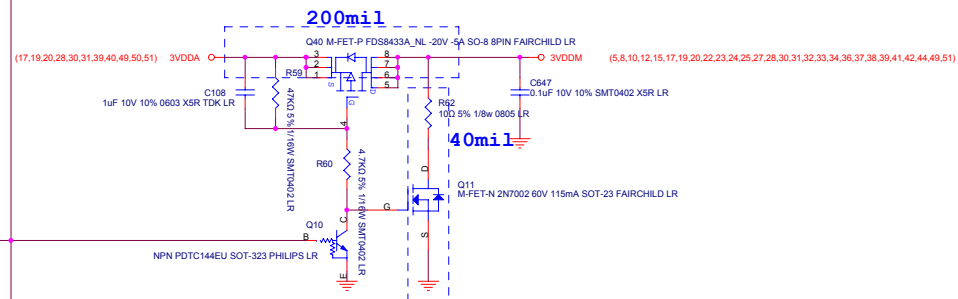
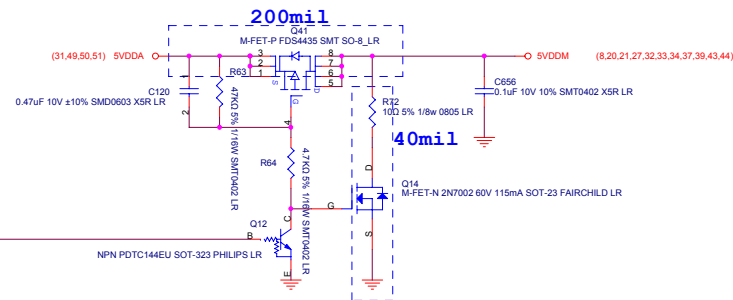
### 3VDDS/5VDDS



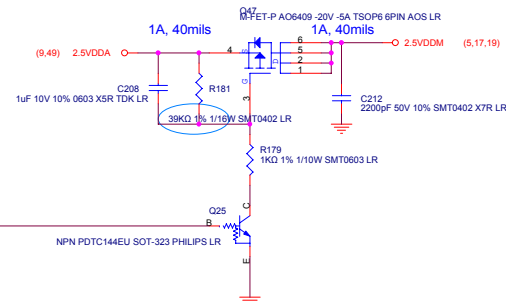
## 1.8VDDS



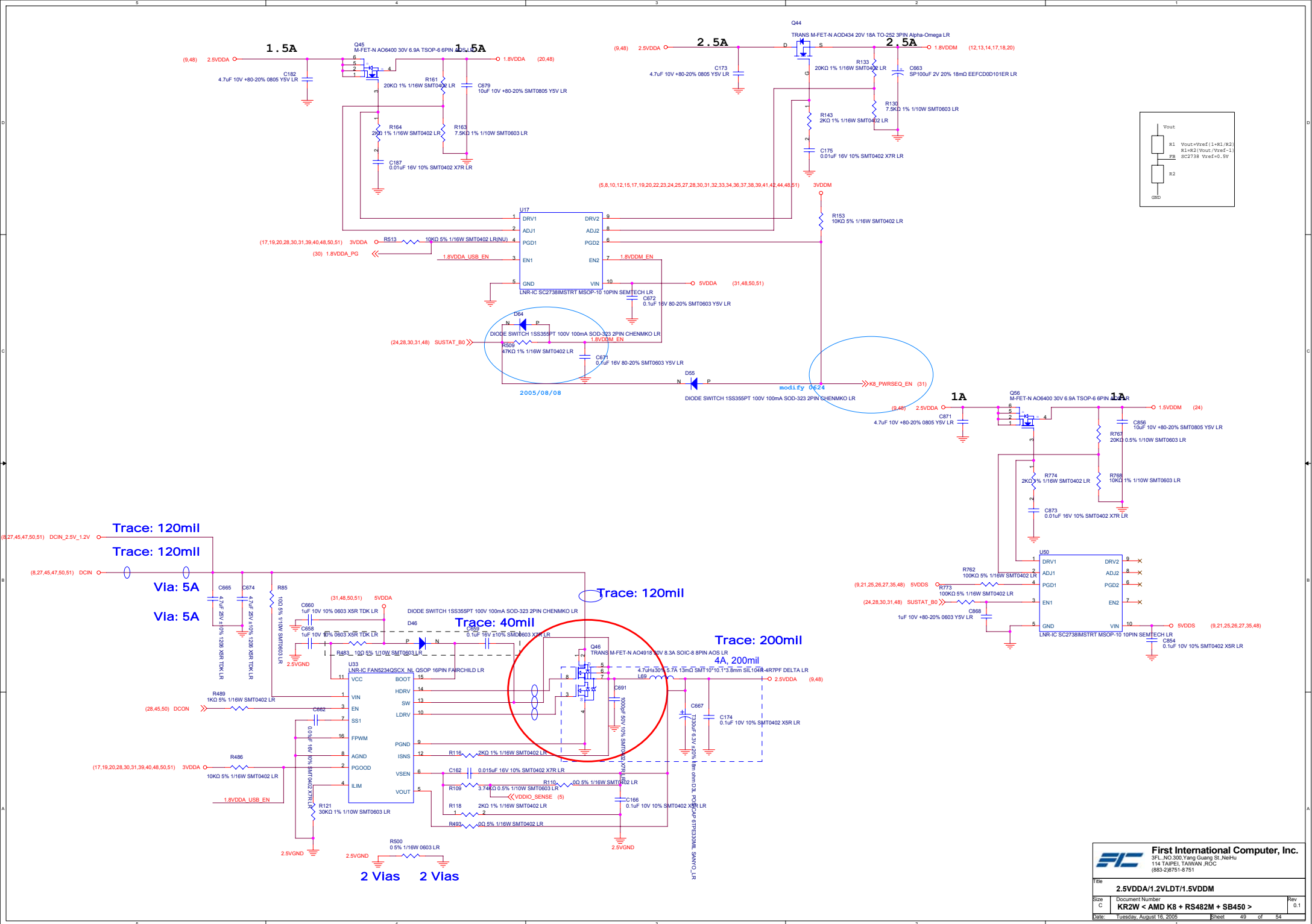
### 3VDDM/5VDDM



## 2.5VDDM

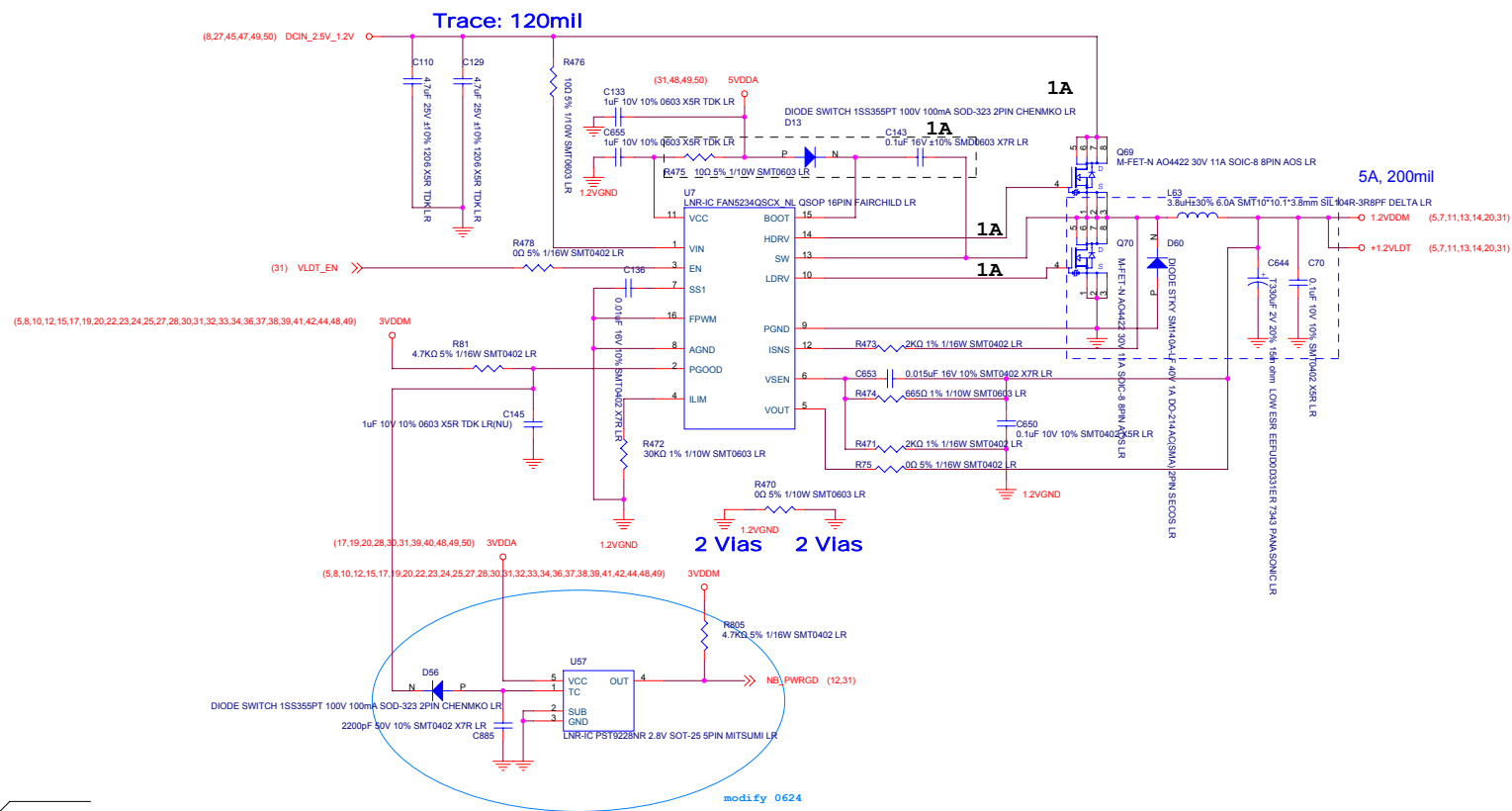


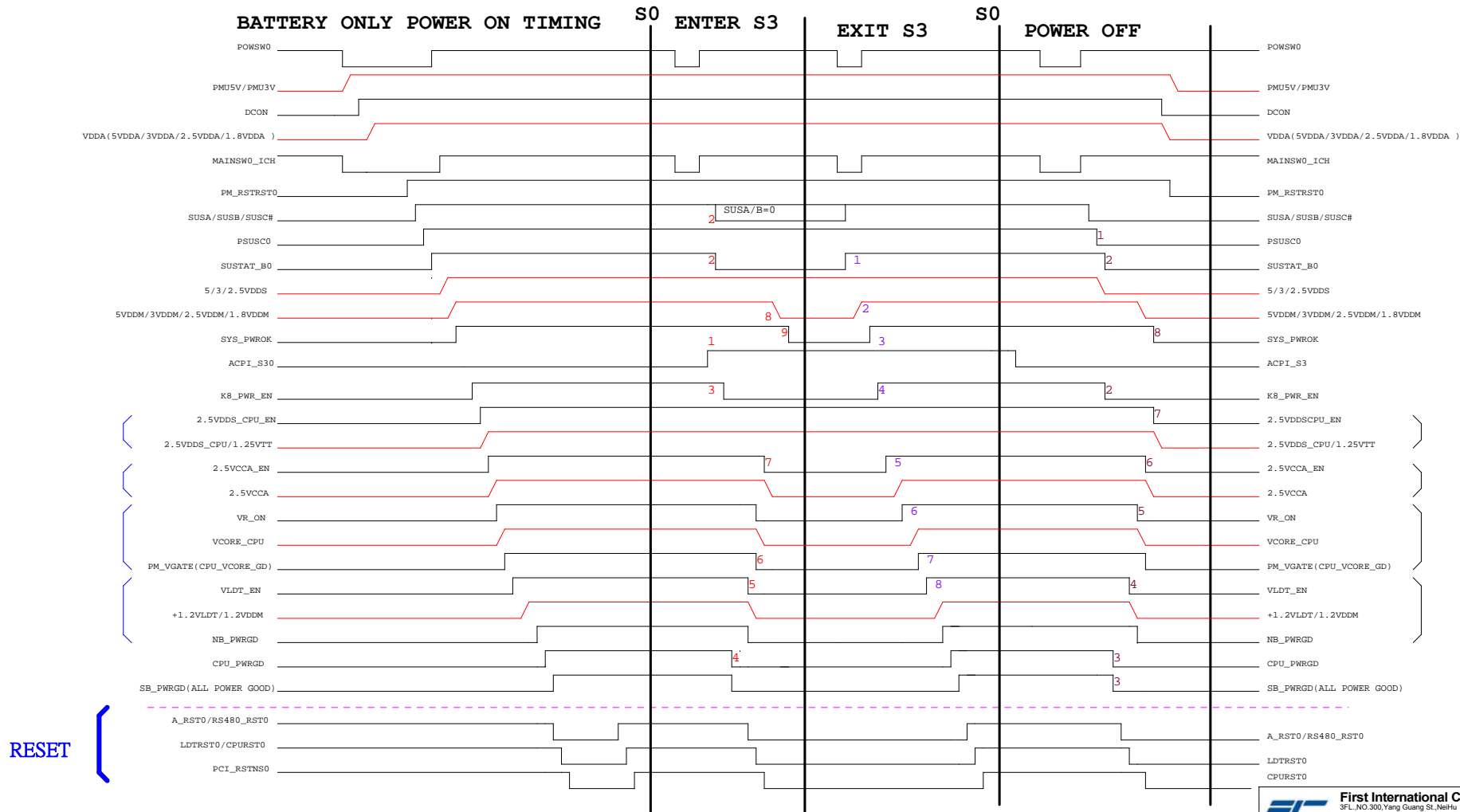
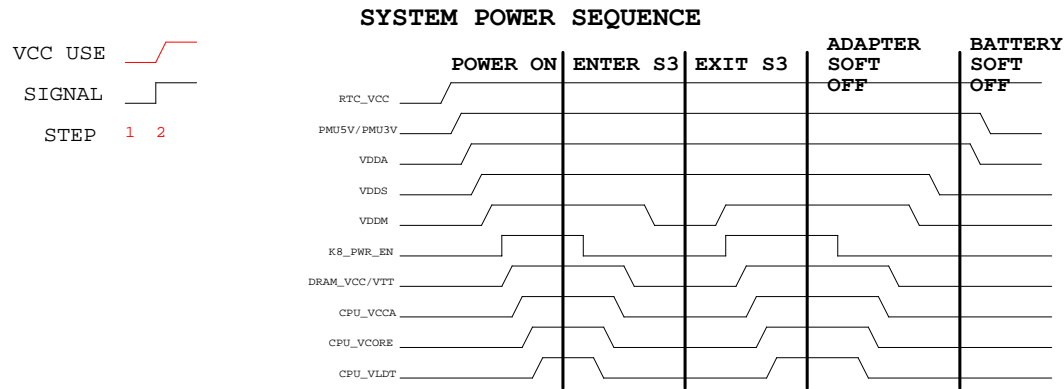






N.B. Core Power and Hypertransport Power





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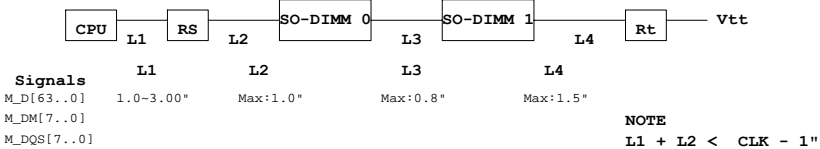
File			Timing
Size	Document Number	Rev	
C	KR2W < AMD K8 + RS482M + SB450 >	0.1	
Date	Tuesday, August 16, 2005	Sheet	52 of 54

## 6.Schematic modify Item and History :

[illegible]

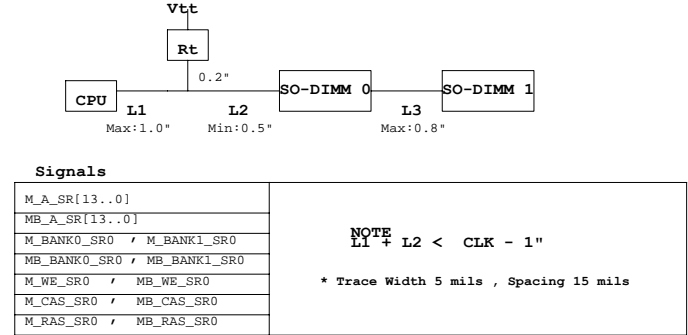
1 DDR SODIMM LAYOUT GUIDE

1. DATA GROUP TOPOLOGY

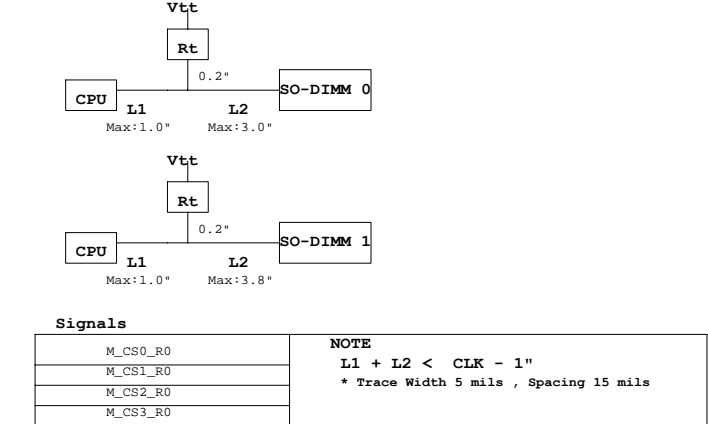


GROUP A	GROUP B	GROUP C	NOTE
M_D[7..0]	M_DM0	M_DQS0	* Group A & Group B & Group C Mismatch must be within 25 mils (Total Length)
M_D[15..8]	M_DM1	M_DQS1	
M_D[23..16]	M_DM2	M_DQS2	* The same Group must be routed in the same layer
M_D[31..24]	M_DM3	M_DQS3	
M_D[39..32]	M_DM4	M_DQS4	* M_DQS[16..0] 5mil trace , 20 mil space M_D[63..0],M_DM[7..0] 5mil trace , 15 mil space
M_D[47..40]	M_DM5	M_DQS5	
M_D[55..48]	M_DM6	M_DQS6	* M_DQS & M_CLK mismatch within 0.5"
M_D[63..56]	M_DM7	M_DQS7	

2. ADDRESS/COMMAND GROUP TOPOLOGY



3. ADDRESS/COMMAND GROUP 2 TOPOLOGY



2 Signal Layout Guide

Signal Group	Maxium Length	Trace Property Normal ( Width : Space ) Differential( S :W:S: W: S )
Hyper Transport Bus	8"	15:5:5:5:15
A_Link Bus	12"	20:5:8:5:20(MS) 20:4:8:4:20(SL)
LVDS BUS	3"	20:5:8:5:20(MS) 20:4:8:4:20(SL)
USB Data	8"	20:5:5:5:20(MS) 20:4:5:4:20(SL)
1394 Bus	8"	20:4:8:4:20(MS) 20:4:12:4:20(SL)
SATA Bus	8"	20:5:8:5:20(MS) 20:4:8:4:20(SL)
PCI / Card / LPC Bus	8"	5:7(MS) 4:6(SL)
IDE Bus	8"	5:7(MS) 4:6(SL)
Clock 66M/33M Hz	6"	5:20(MS) 4:20(SL)

\* Differential Signal Layout  
Should Be The Same Length

For Example :

LVDS\_TXCLK\_LP & LVDS\_TXCLK\_LN  
USB20\_P0+ & USB20\_P0-

Should Be The Same Length ASAP